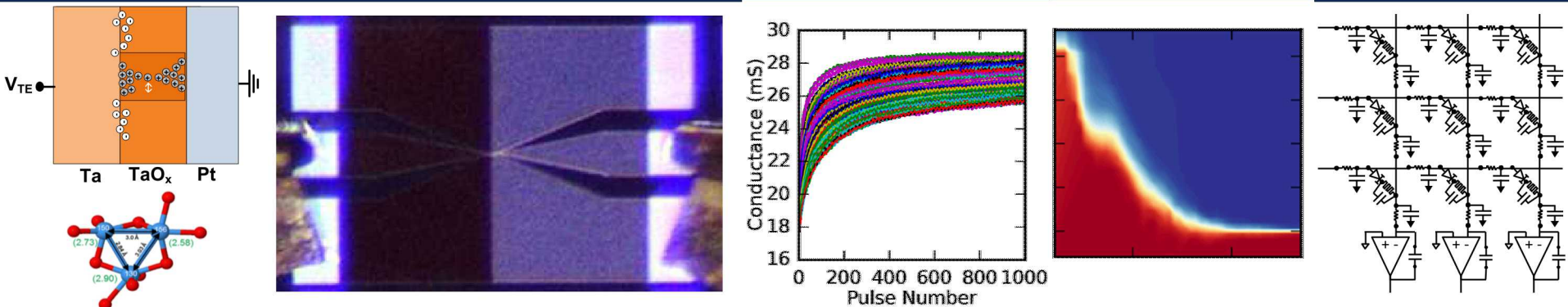


Energy Efficient Neuromorphic Algorithm Acceleration Enabled by Resistive Memory (ReRAM) Crossbars

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Sandia National Laboratories

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Microelectronics Reliability & Qualification working meeting

# Outline

- **Intro and Motivation**
- **ReRAM-Based Accelerator Key Concepts**
- **ReRAM-Based Accelerator Model**
- **Conclusion**

# Why do we need more efficient computers?

- **Google Deep Learning Study**

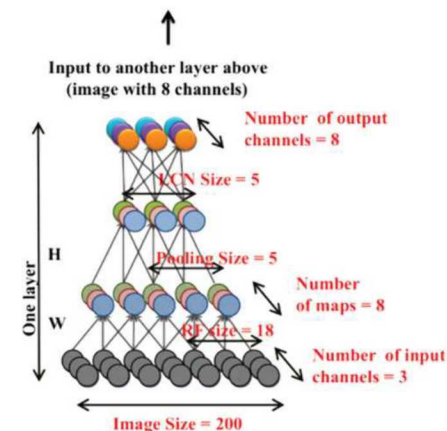
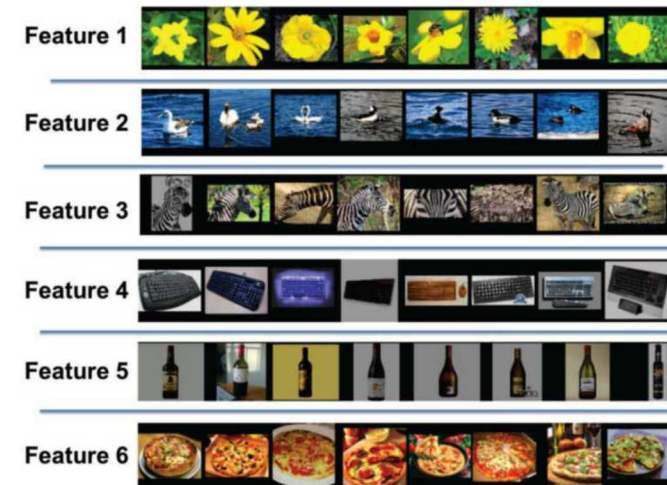
- 16000 core, 1000 machine GPU cluster
- Trained on 10 million 200x200 pixel images
- Training required 3 days
- Training set size set by what can be completed in less than one week

- **What would they like to do?**

- ~2 billion photos uploaded to internet per day (2014)
- Can we train a deep net on one day of image data?
- Assume 1000x1000 nominal image size, linear scaling (both assumptions are unrealistically optimistic)
- *Requires 5 ZettaIPS to train in 3 days (ZettaIPS= $10^{21}$  IPS; ~5 billion modern GPU cores)*
- Data is increasing exponentially with time

- **Need  $>10^{16}$ - $10^{18}$  instruction-per-second on 1 IC**

- Less than 10 fJ per instruction energy budget



Q. Le, IEEE ICASSP 2013

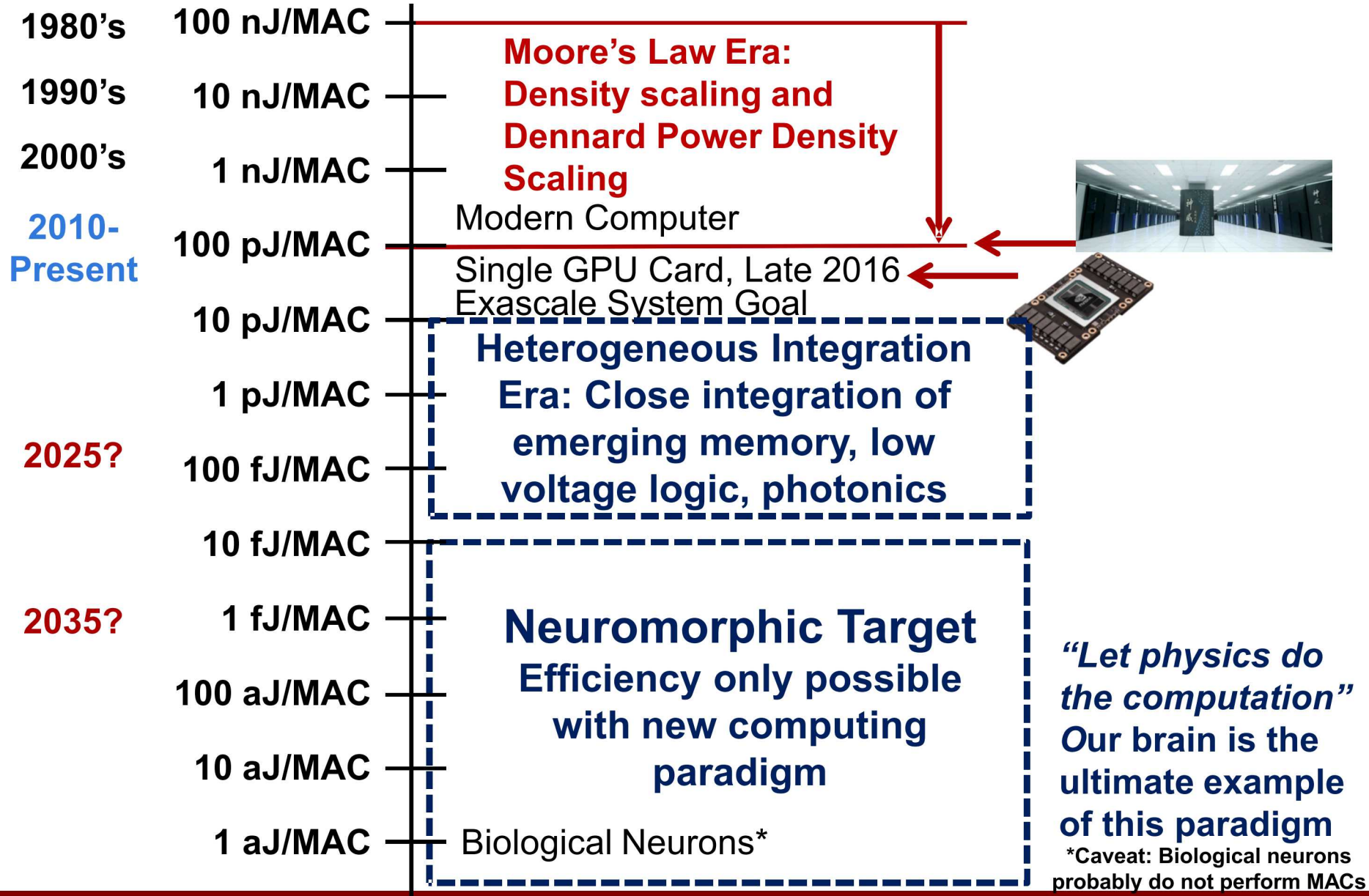
# Where Are we Today?

- **Single Unit: Nvidia Tesla P100 GPU**
  - Most advanced GPU processor specs, released late 2016
  - Target's deep learning and neural applications
  - 20 TFLOPs 16 bit peak performance w/ peak power dissipation of 300W
  - 70 GFLOPs/watt or about 15 pJ/FLOP (16 bit)
- **Supercomputer: Sunway TaihuLight (China)**
  - Top supercomputer in the world
  - ShenWei processor
  - 90 PFLOPs peak, 15 MW power
  - 6 GFLOPs/W or about 170 pJ/FLOP
- **Need >1000x improvement to tackle *internet-scale* problems**





# Evolution of Computing Machinery

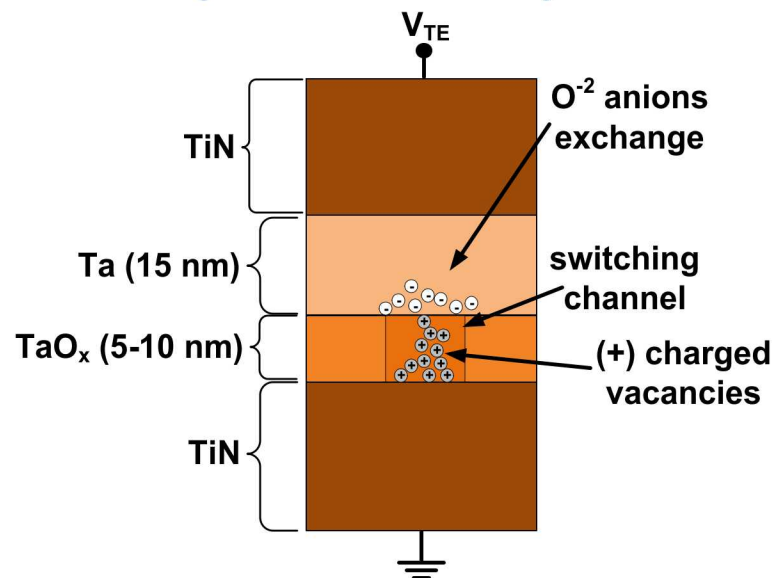


# Outline

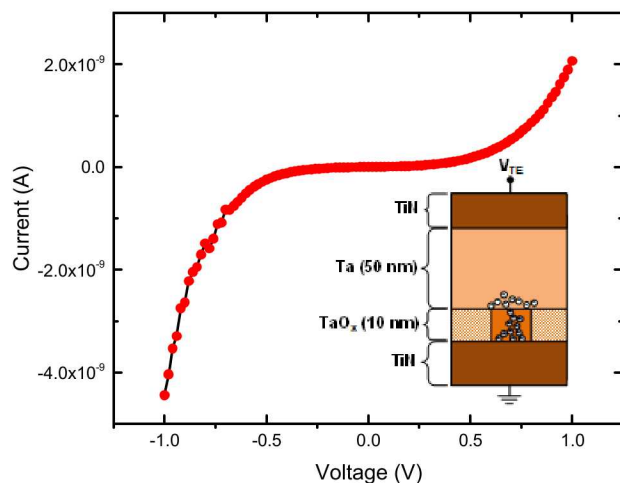
- **Intro and Motivation**
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# Metal Oxide Resistive RAM (ReRAM)

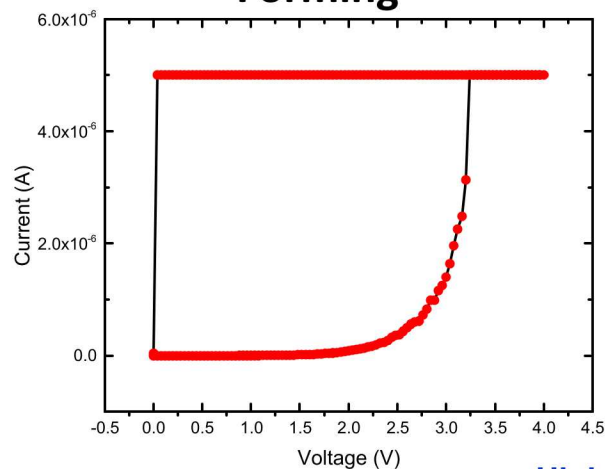
- Sandia TiN/Ta/TaO<sub>x</sub>/TiN example device
- Starts as insulating MIM structure
- Forming: remove O<sup>2-</sup> → soft breakdown
- Bipolar resistance modulation
- Excellent memory attributes: Switching in less than 1ns, less than 1 pJ demonstrated, scaling to 5nm, >10<sup>12</sup> write cycles



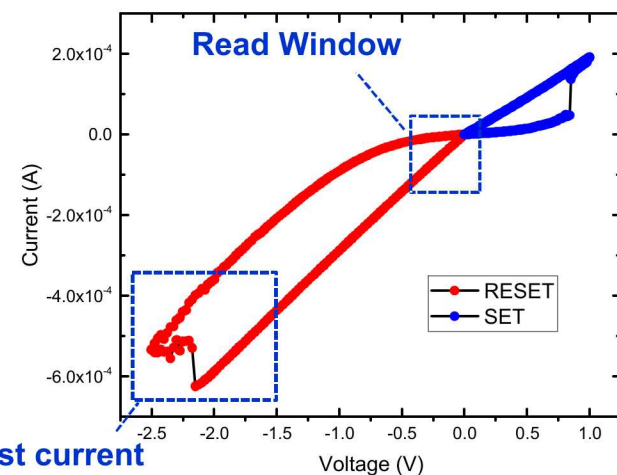
Pre-Form I/V



Forming



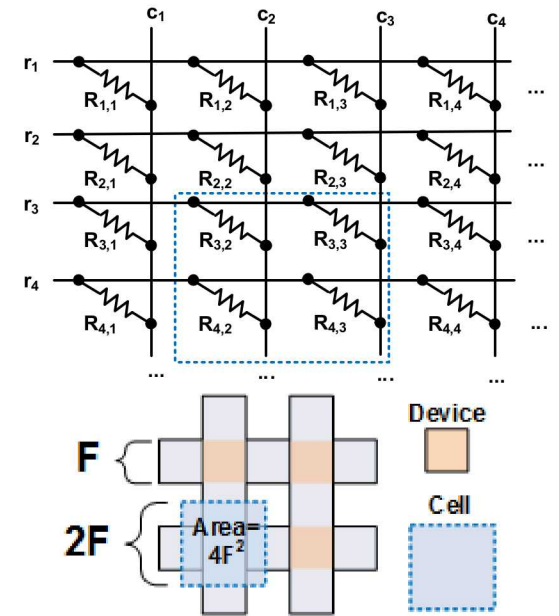
SET-RESET



Highest current  
switching process

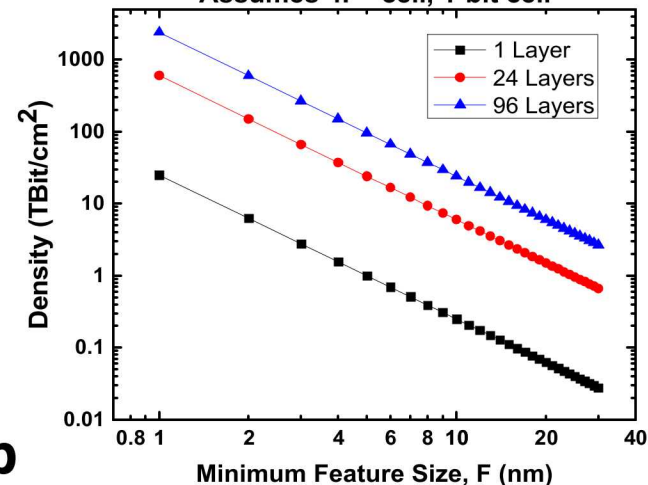
# Crossbar Theoretical Limits

- Potential for 100 Tbit of ReRAM on chip
- If each can perform 1M computations of interest per second (1 M-op):
  - $10^{12}$  active devices/chip x  $10^6$  cycle per second  $\rightarrow 10^{18}$  comps per second per chip
  - Exascale-computations per sec on one chip!
- In order to not melt the chip, entire area must be limited to  $\sim 100\text{W}$
- Allowed energy per operation =  $P \times t/\text{op} = 100\text{W} / 10^{18} = 10^{-16} = 100 \text{ aJ}/\text{operation}$
- 10nm line capacitance = 10 aF
- Can charge line to 1V with 10 aJ
- Drawback: “only”  $\sim 100\text{B}$  transistors/chip



ReRAM Density vs Min. Feature Size

Assumes 4F<sup>2</sup> cell, 1-bit cell



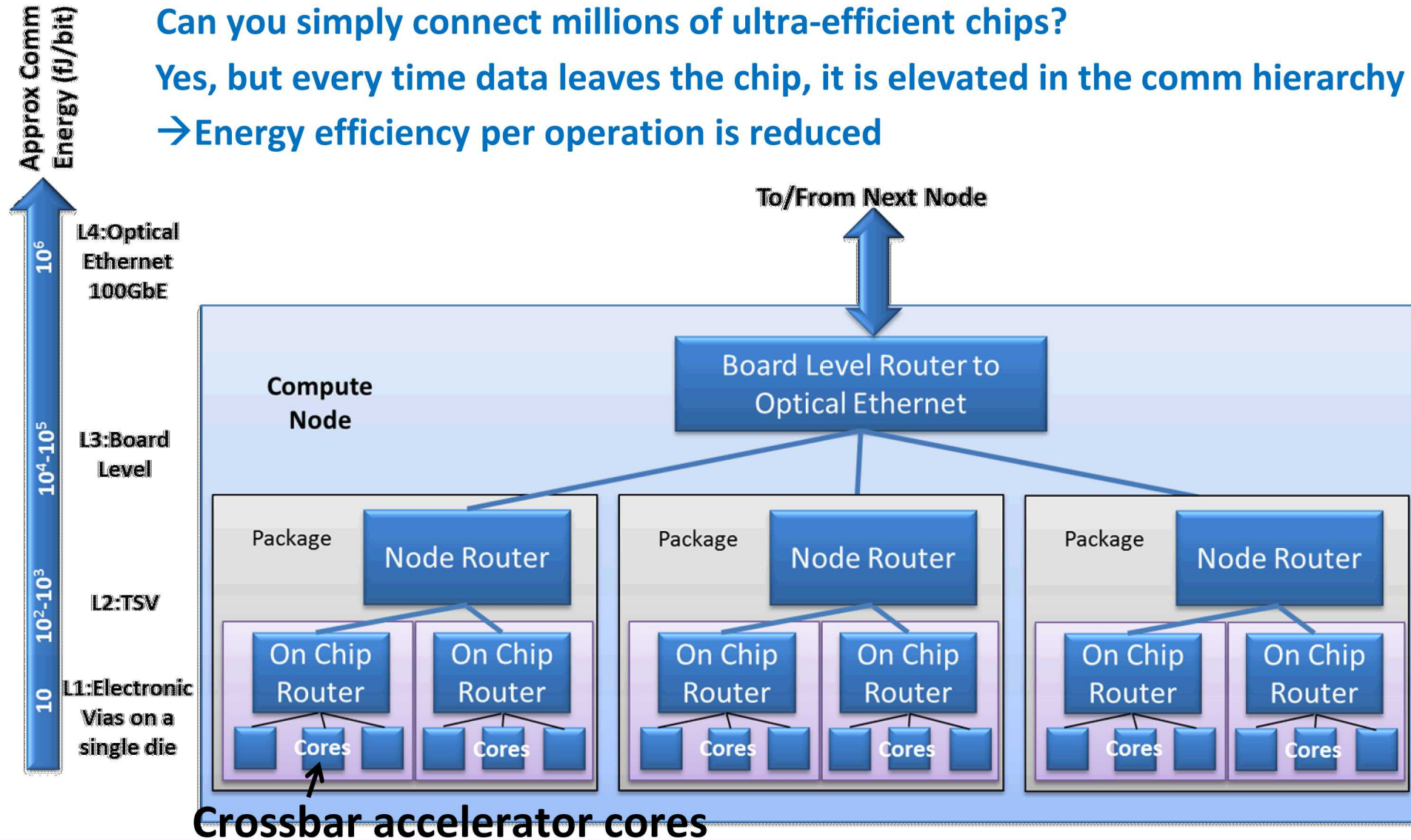


# Why is it essential to cram so many computations on a single chip?

Can you simply connect millions of ultra-efficient chips?

Yes, but every time data leaves the chip, it is elevated in the comm hierarchy

→ Energy efficiency per operation is reduced



# How does a crossbar perform a useful computation per device?

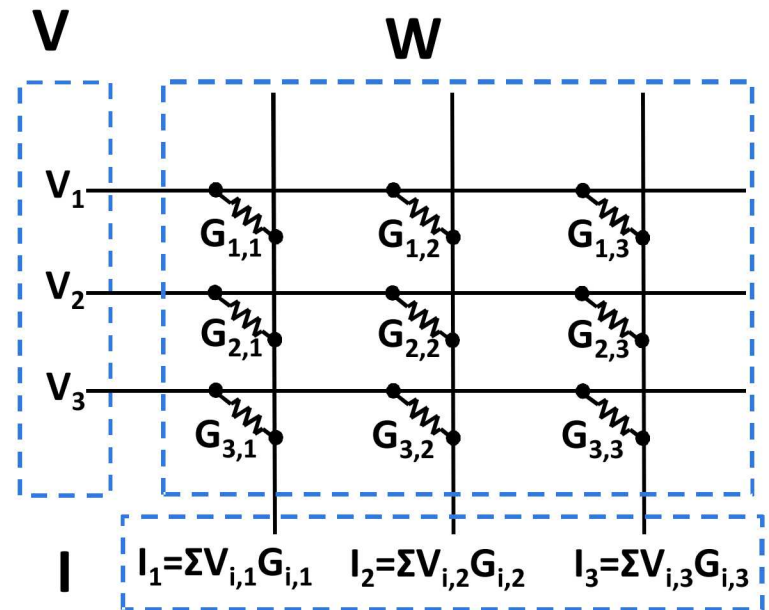
- Electronic Vector Matrix Multiply

**Mathematical**

$$V^T W = I$$

$$\begin{bmatrix} V_1 & V_2 & V_3 \end{bmatrix} \begin{bmatrix} W_{1,1} & W_{1,2} & W_{1,3} \\ W_{2,1} & W_{2,2} & W_{2,3} \\ W_{3,1} & W_{3,2} & W_{3,3} \end{bmatrix} = \begin{bmatrix} I_1 = \sum V_{i,1} W_{i,1} & I_2 = \sum V_{i,2} W_{i,2} & I_3 = \sum V_{i,3} W_{i,3} \end{bmatrix}$$

**Electrical**

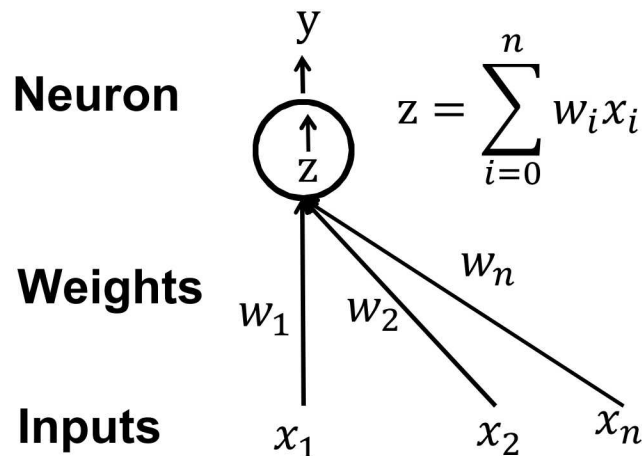


# Basics of Neural Networks

## Simple Network: Backpropagation

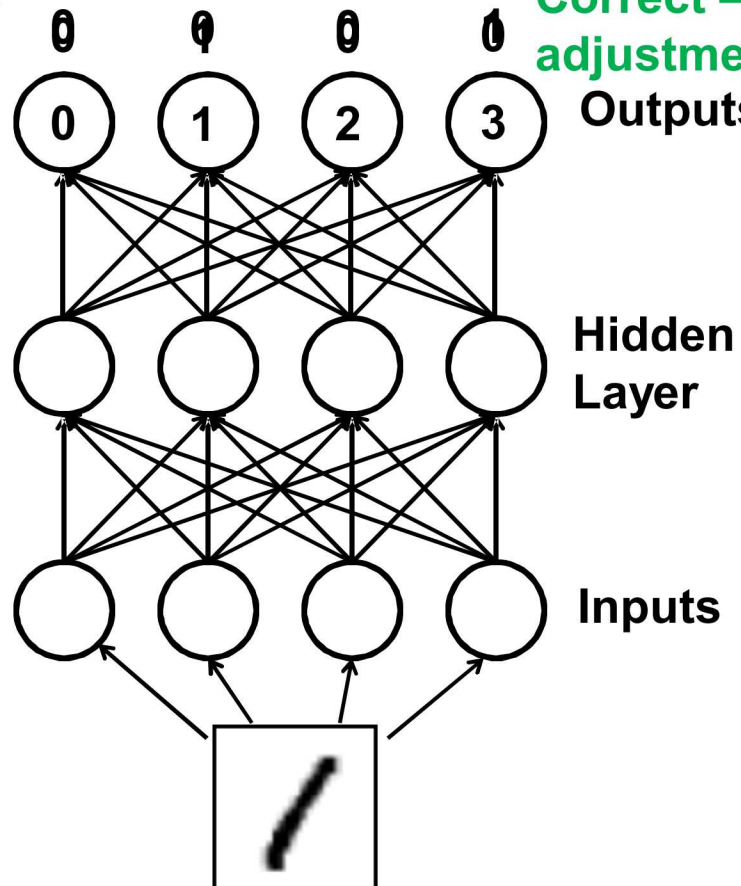
### Basic Building Block

$$y = \frac{1}{1 + e^{-z}}$$

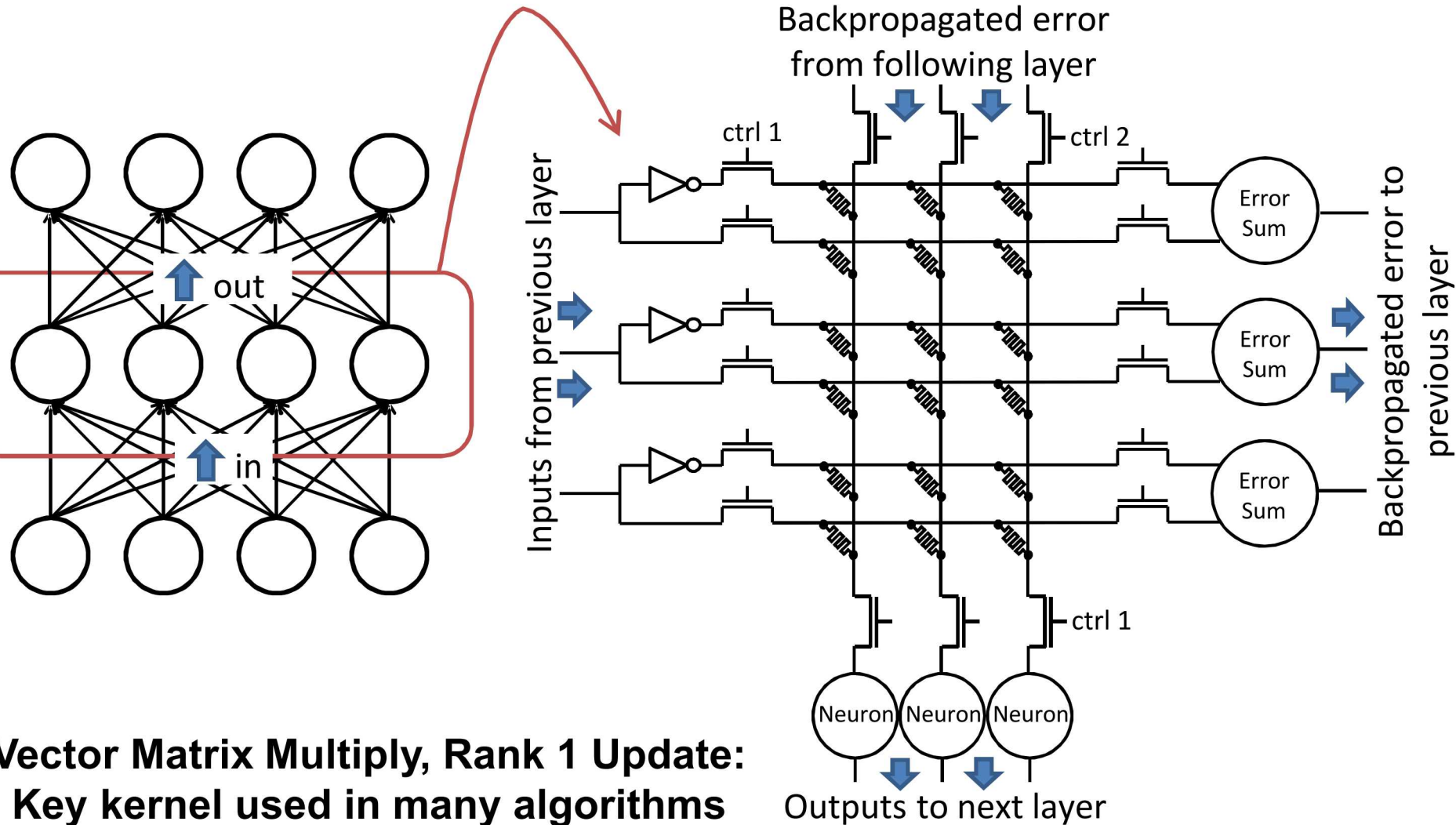


**Incorrect –  
adjust**

**Correct – no  
adjust  
Outputs**

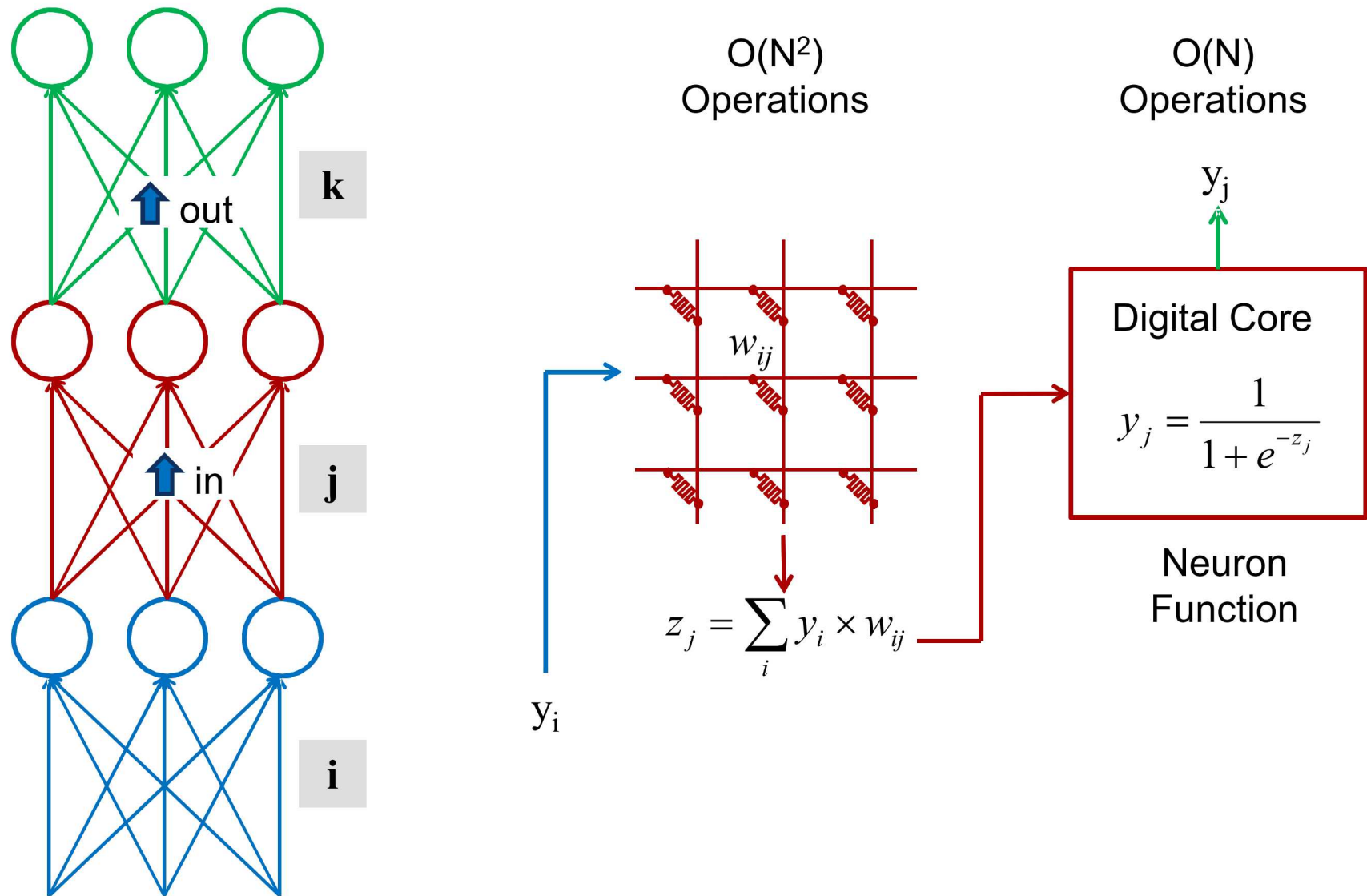


# Mapping Backprop to a Crossbar

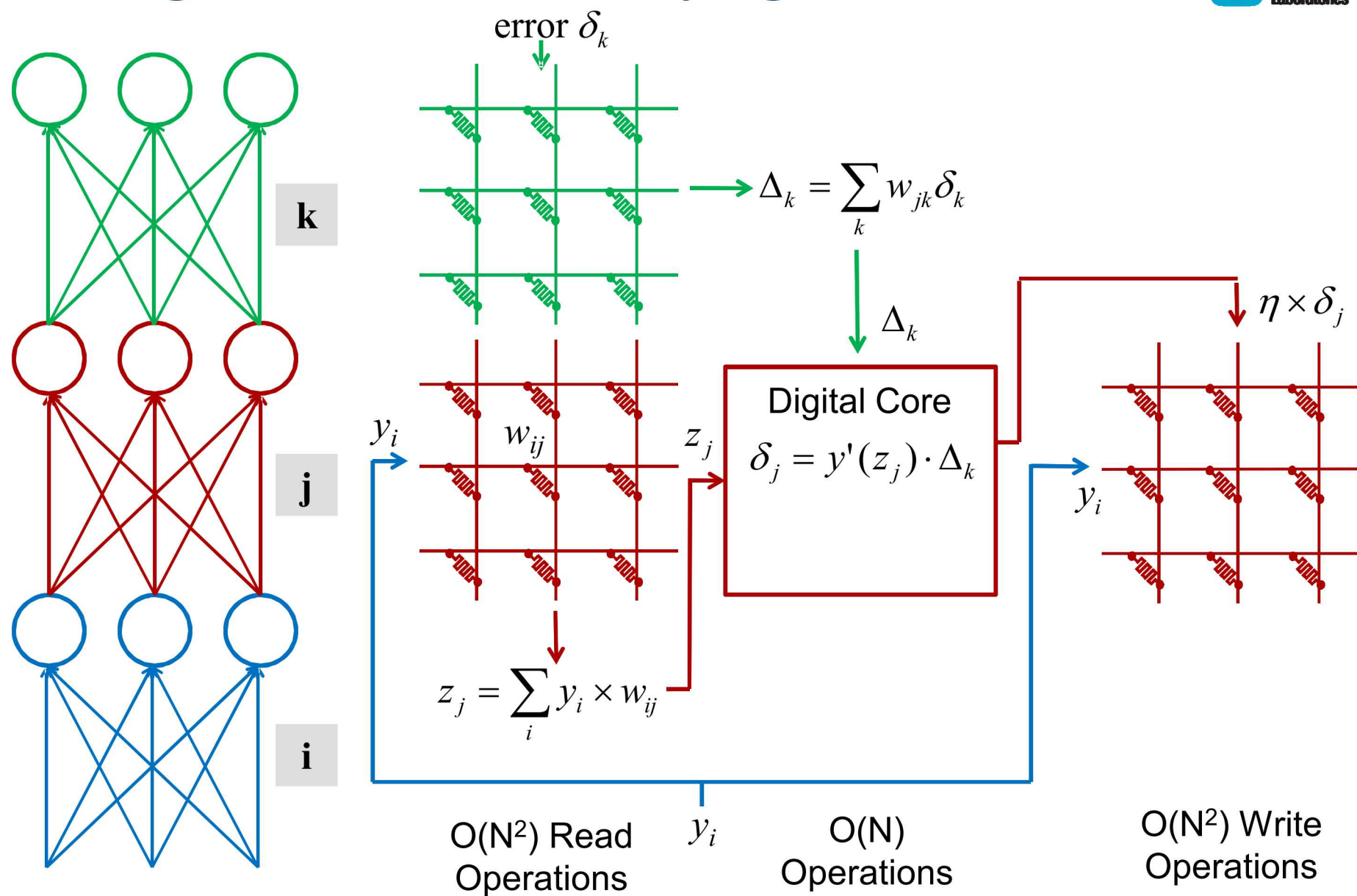




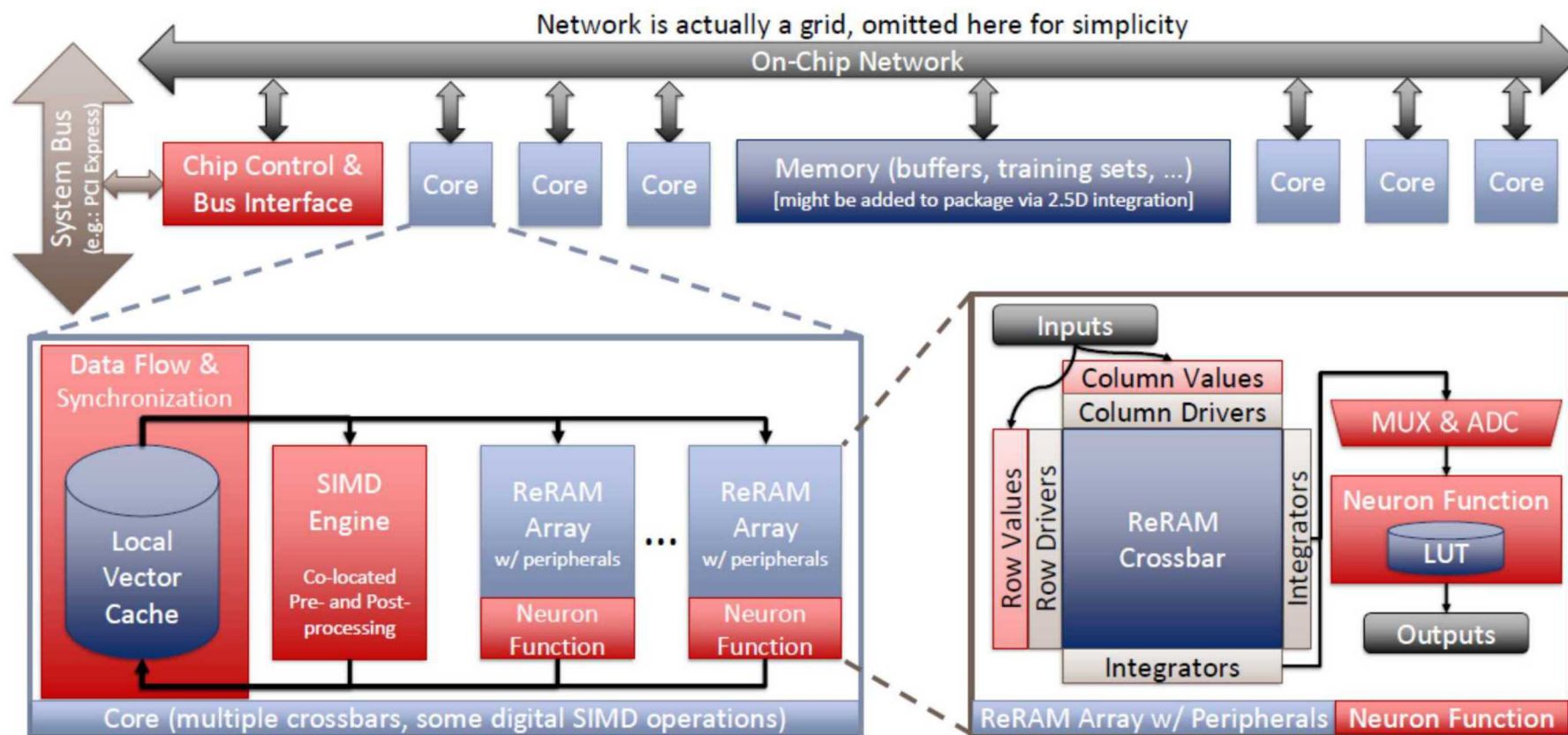
# Analog Core: Forward Propagation



# Analog Core: Back Propagation



# Accelerator Architecture



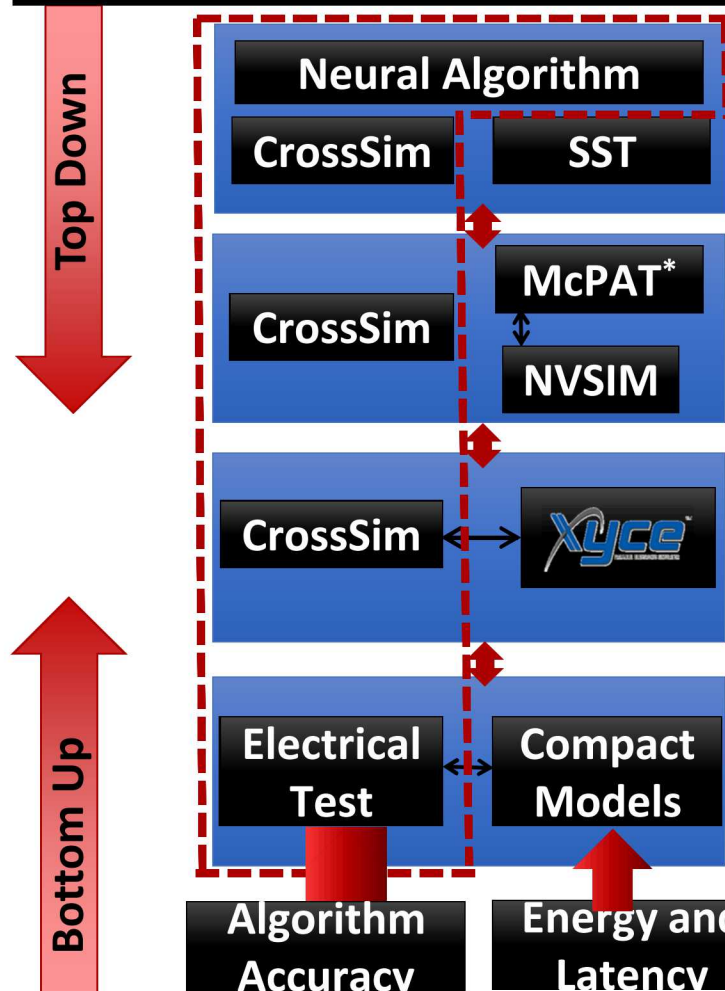
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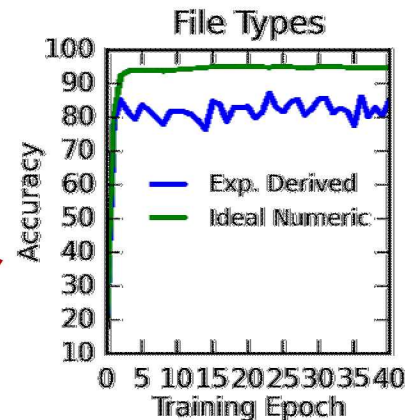


# Device to Algorithm Model

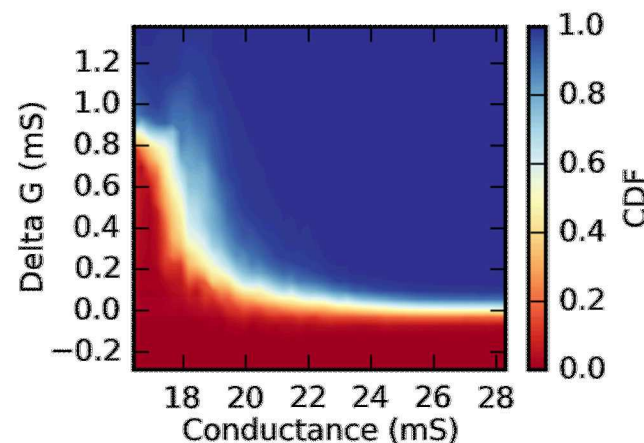
What device properties are needed?



Neural Algorithm Level Model

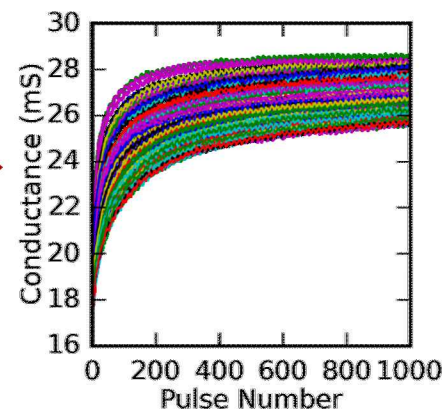


Computer Architecture Level Model



Circuit Level Models

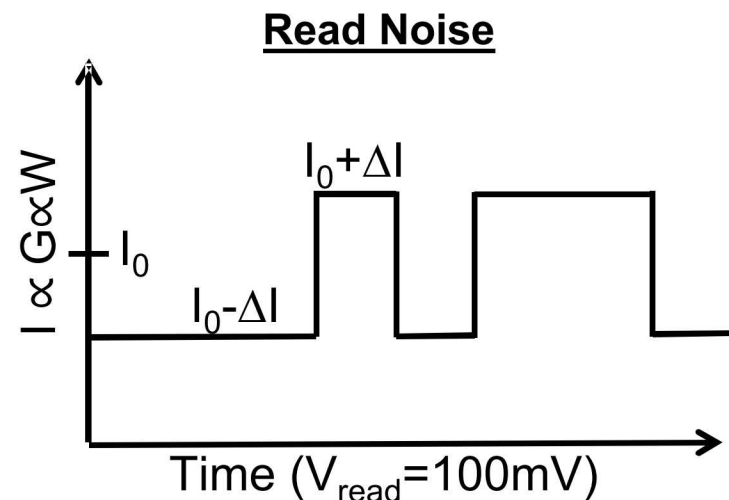
Device Level Models



How do specific devices work in system?

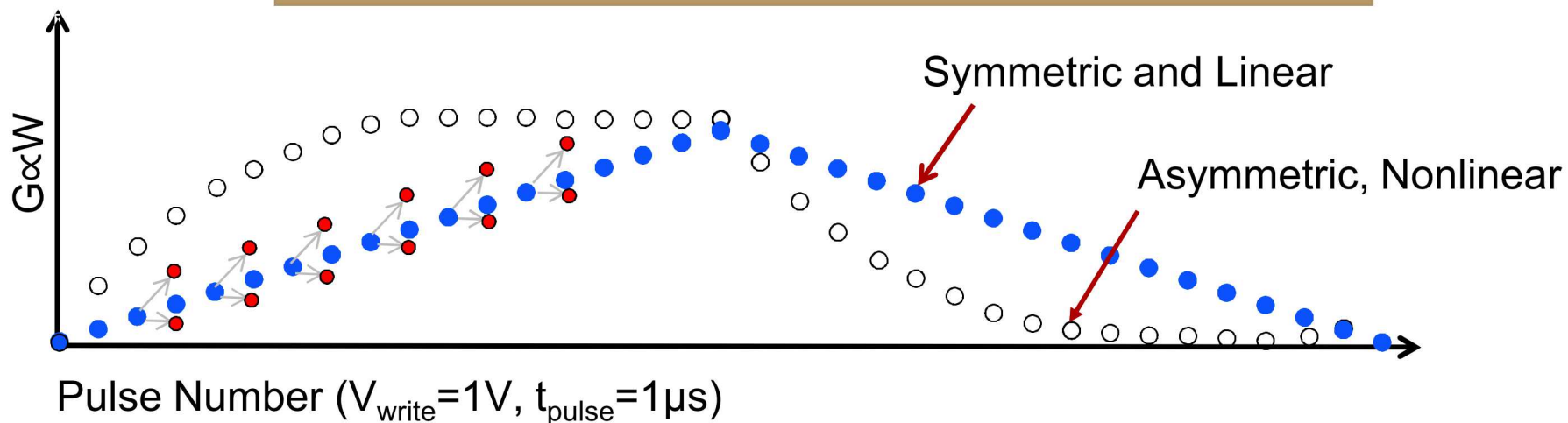
# Experimental Device Nonidealities

- Ideally weight would increase and decrease linearly proportional to learning rule result
- Experimental devices have several nonidealities: **Write Variability**, **Write Nonlinearity**, **Asymmetry**, **Read Noise**
- Circuits also have A/D, D/A noise, parasitics



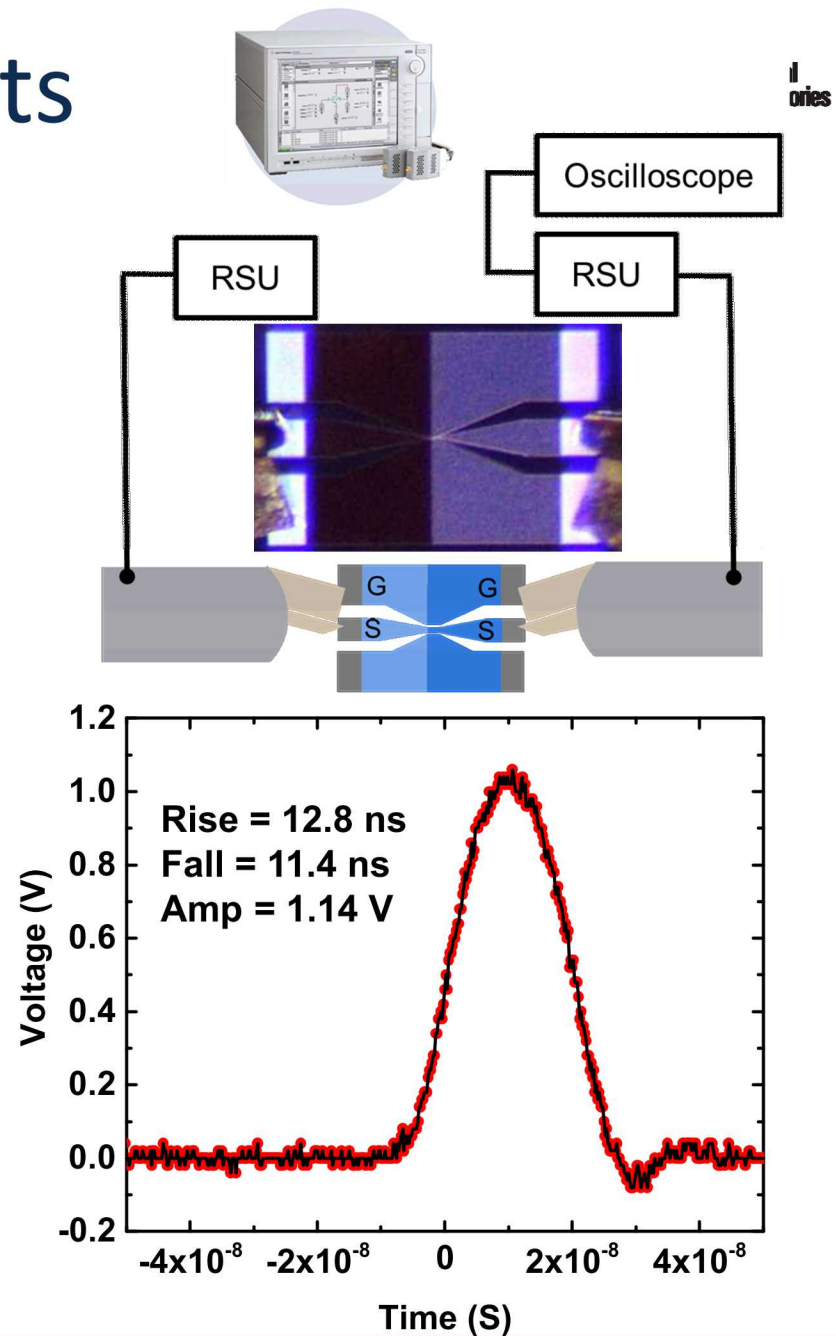
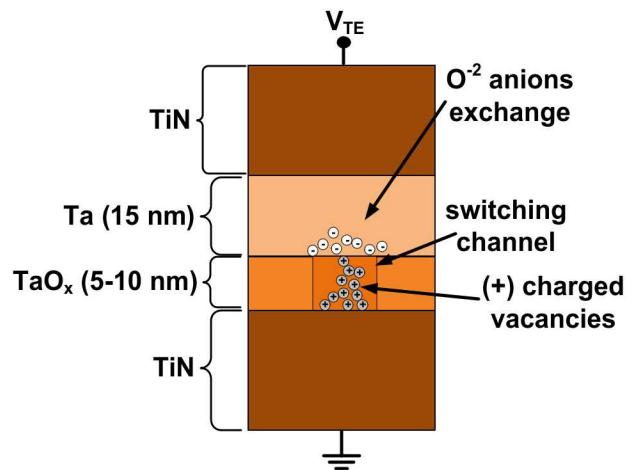
## Conductance versus Pulse

● = Ideal    ↗↘ = Write Variability    ○ = Nonlinear

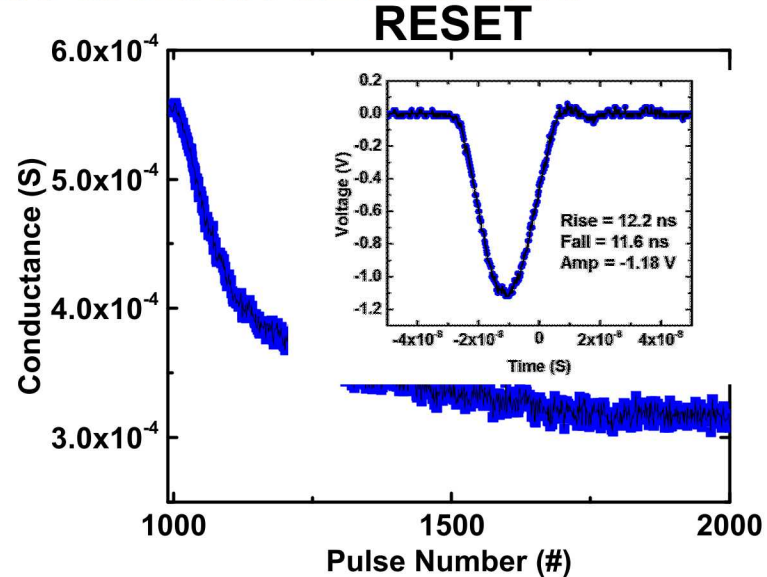
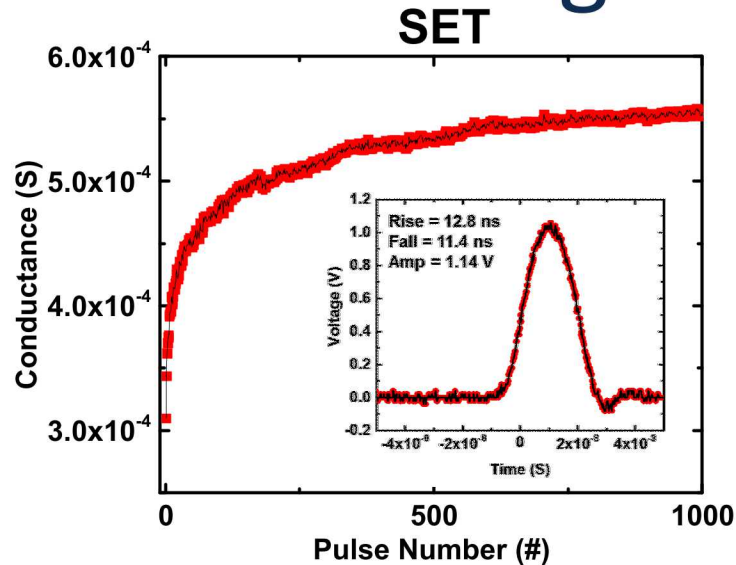


# ReRAM Measurements

- DC Current-voltage “loops” sweeps are not time-controlled
  - Excessive heating and early wearout
  - Do not provide info on dynamics
- Physical switching < 10ns
- Need pseudo RF setup to measure
  - Ground/signal, conductor backed
  - Agilent B1530 module
  - 10 ns RT/FT, 10 ns PW
  - 1 V nominal, ~140 mV overshoot

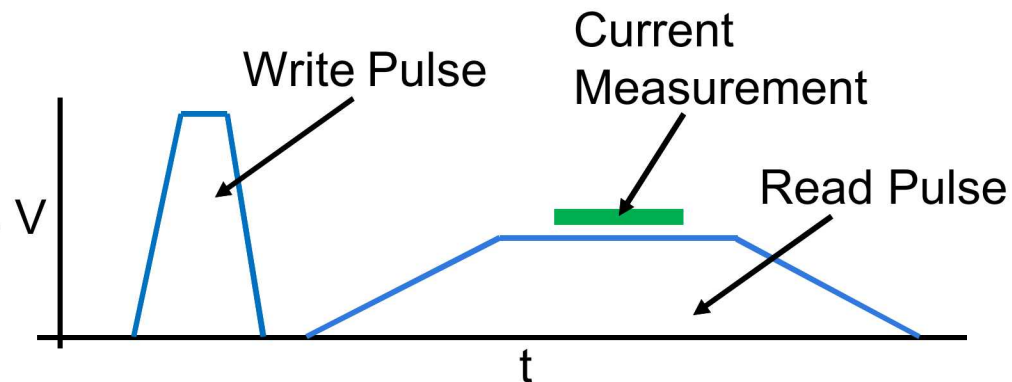


# ReRAM Analog Characterization



- Use as a neuromorphic weight requires precise analog tuning
- Dataset requires 1000 repeated SET and RESET pulses
- Nominal pulse values

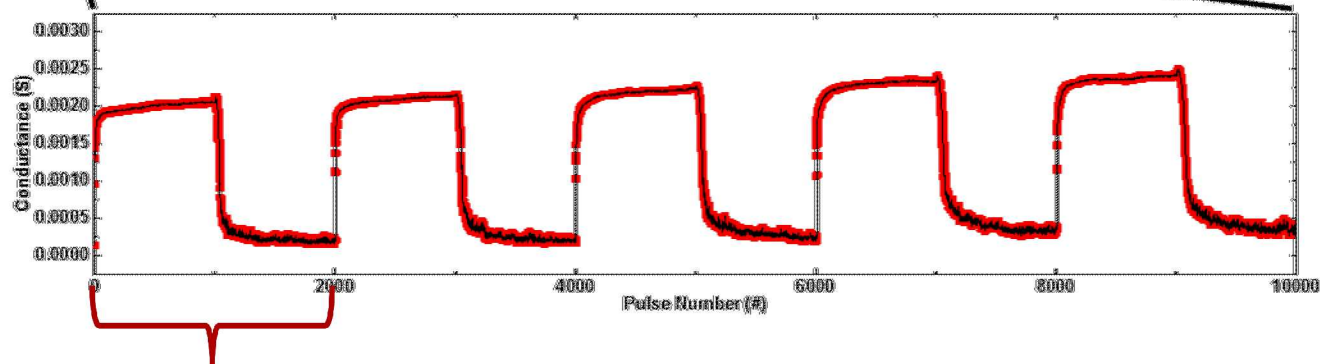
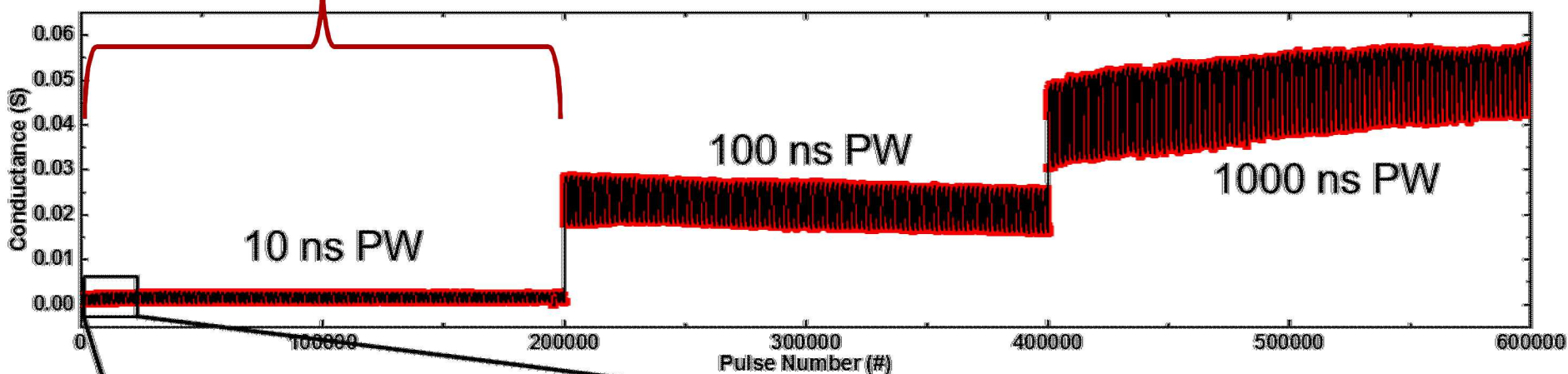
- SET: +1V 10ns RT/PW/FT
- RESET: -1V 10ns RT/PW/FT
- READ: 100 mV 1 ms RT/PW/FT





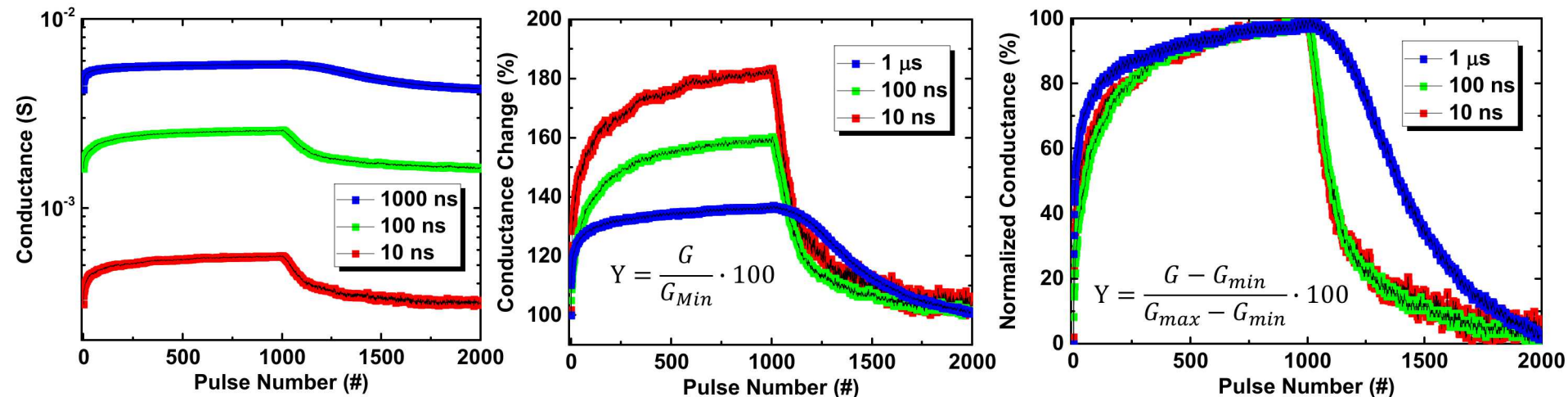
# Pulse Width Analog Measurements

100 on→off cycles,  
(200k pulses)



2000 pulses per  
on→off cycle

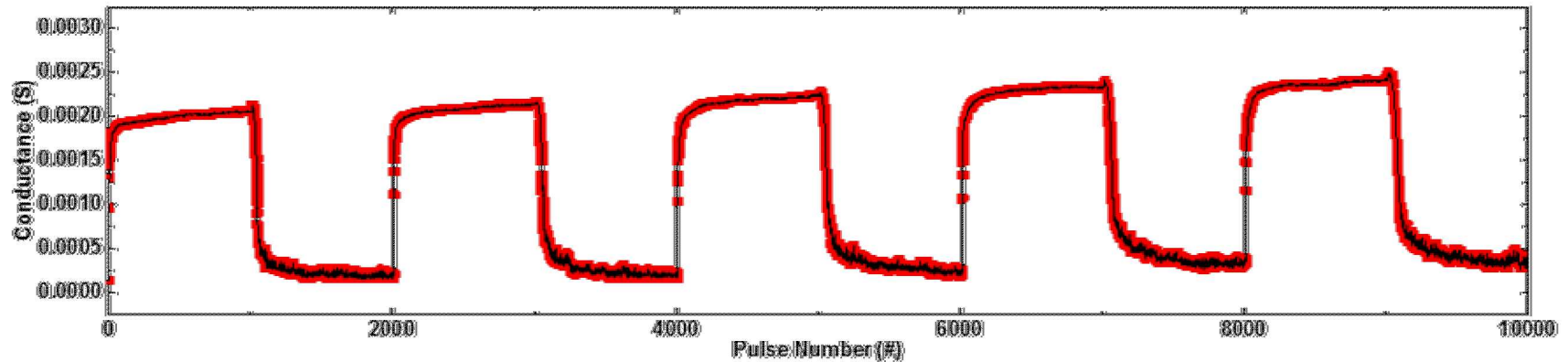
# Effect of Pulse Width and Edge Time Sandia National Laboratories



- Shorter pulses may be employed to lower conductance switching range
- Linearity qualitatively similar across Pulse Width (PW) and Edge Time (ET)
  - Best for SET at 100 ns
  - Best for RESET at 1  $\mu$ s
- Relative conductance change increased with shorter Pulse Width / Edge Time

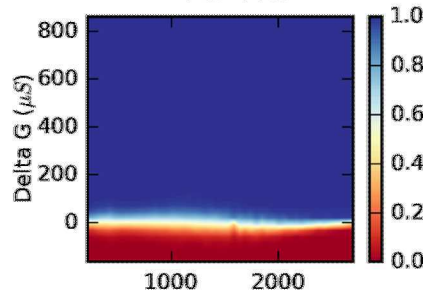
Nominal Pulse Voltage Values: SET: +1 V RESET: -1 V

# Repeated Pulsed Cycling

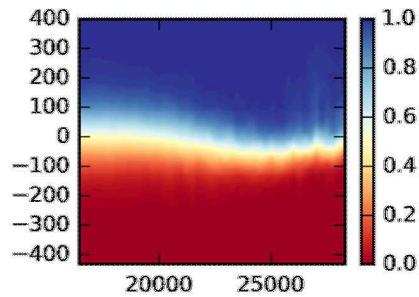


RESET

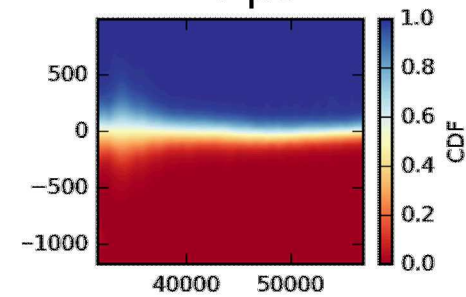
10 ns



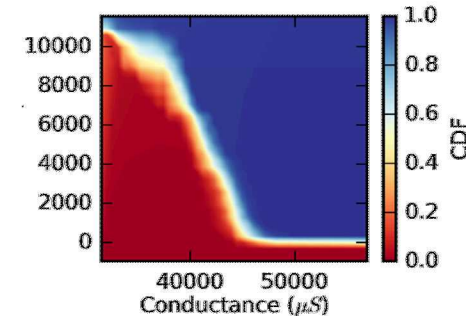
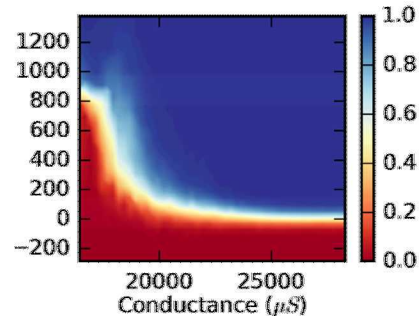
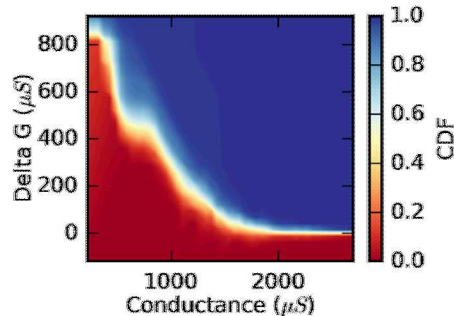
100 ns



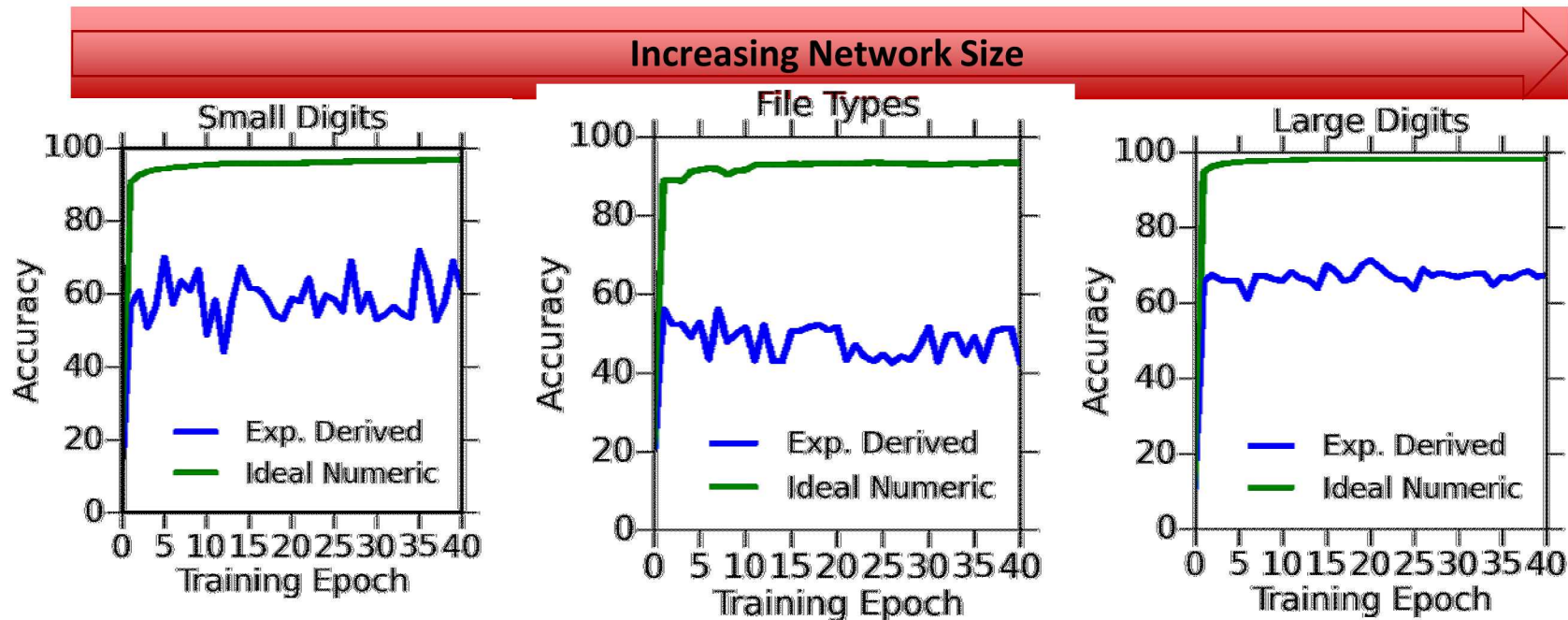
1  $\mu s$



SET



# TaOx ReRAM in Backprop Training

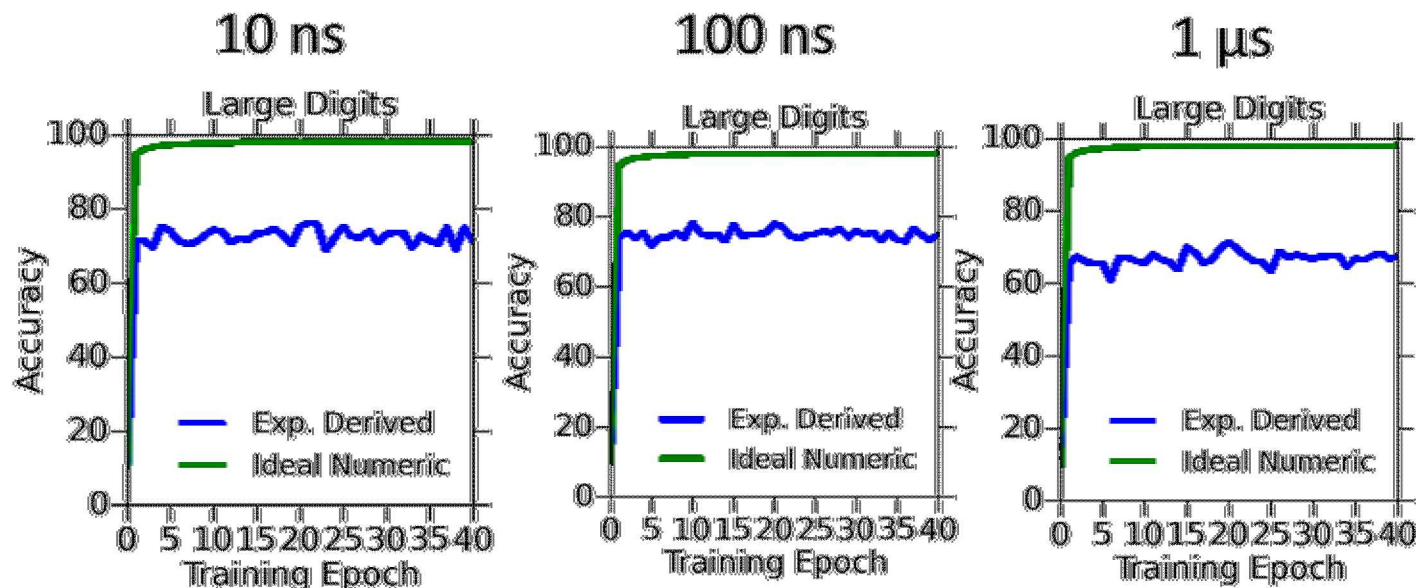


Data set	# Training Examples	# Test Examples	Network Size
UCI Small Digits[1]	3,823	1,797	64×36×10
File Types[2]	4,501	900	256×512×9
MNIST Large Digits[3]	60,000	10,000	784×300×10



# Modeling Effect of Pulse Time

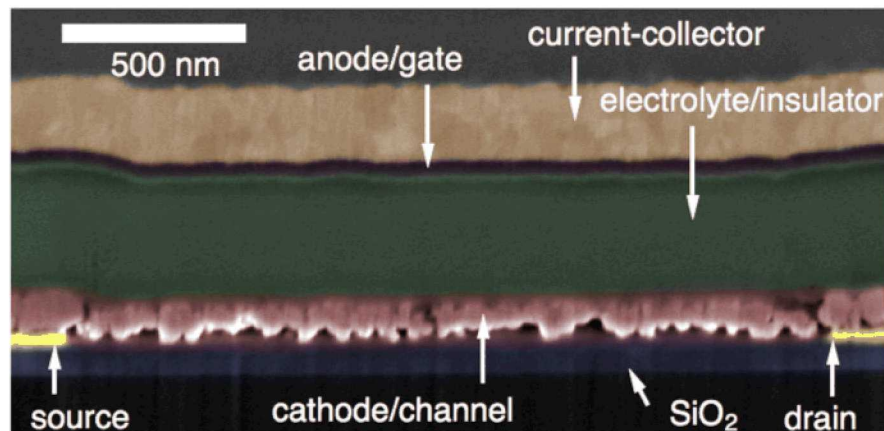
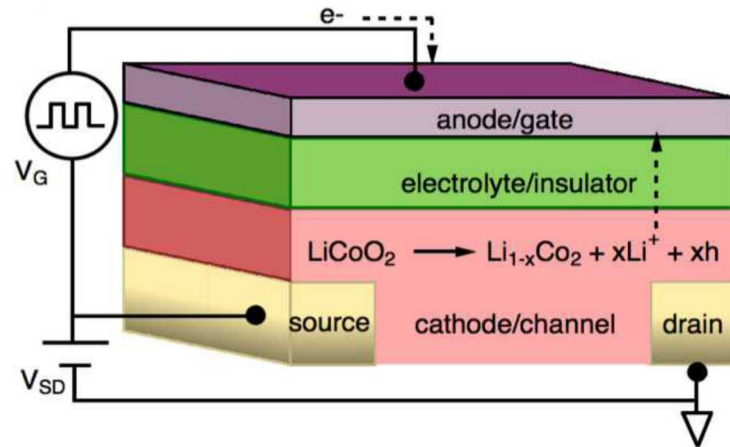
Increasing Network Size



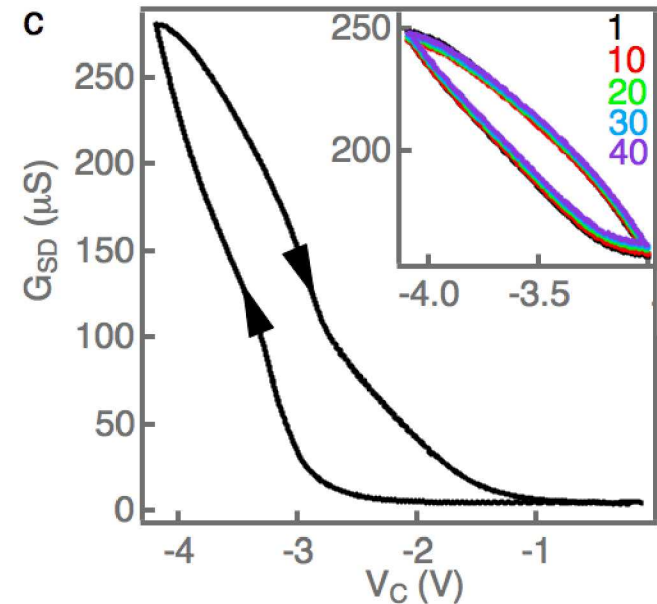
TaOx	Large Images	Small Images	File Types
10 ns	84.45%	71.40%	77.67%
100 ns	78.48%	89.48%	67.78%
1 us	71.48%	71.84%	56.33%

**How can training accuracy be improved?**

# Li-Ion Synaptic Transistor for Analog Computation (LISTA)

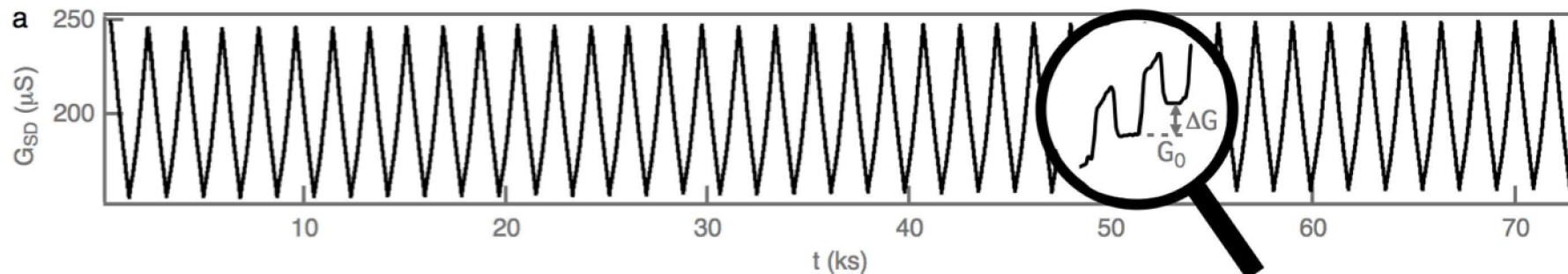


## G-V for LISTA Transistor

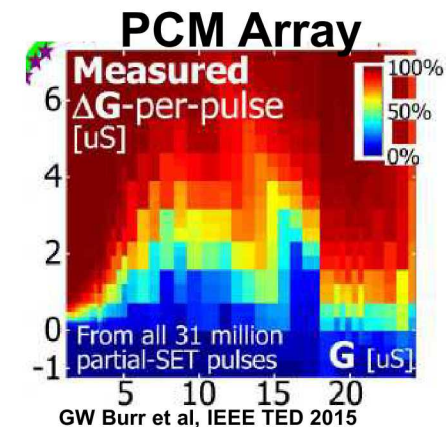
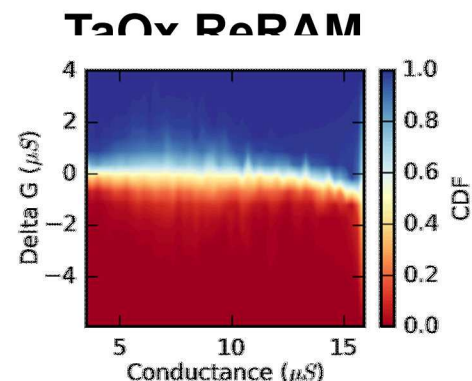
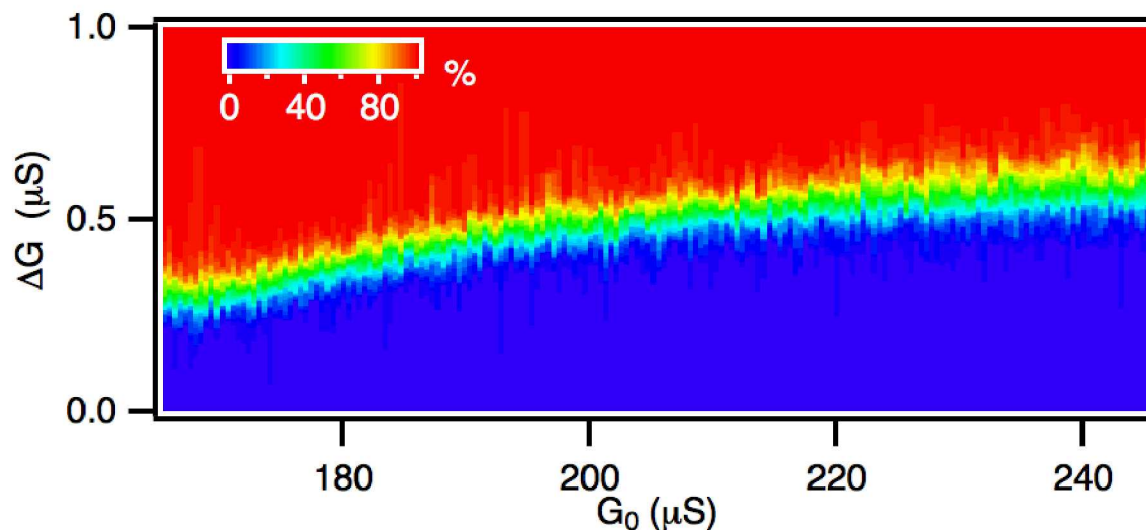


E. Fuller et al, *Adv Mater*, accepted 2017

# Analog State Characterization



**LISTA > 200 states**

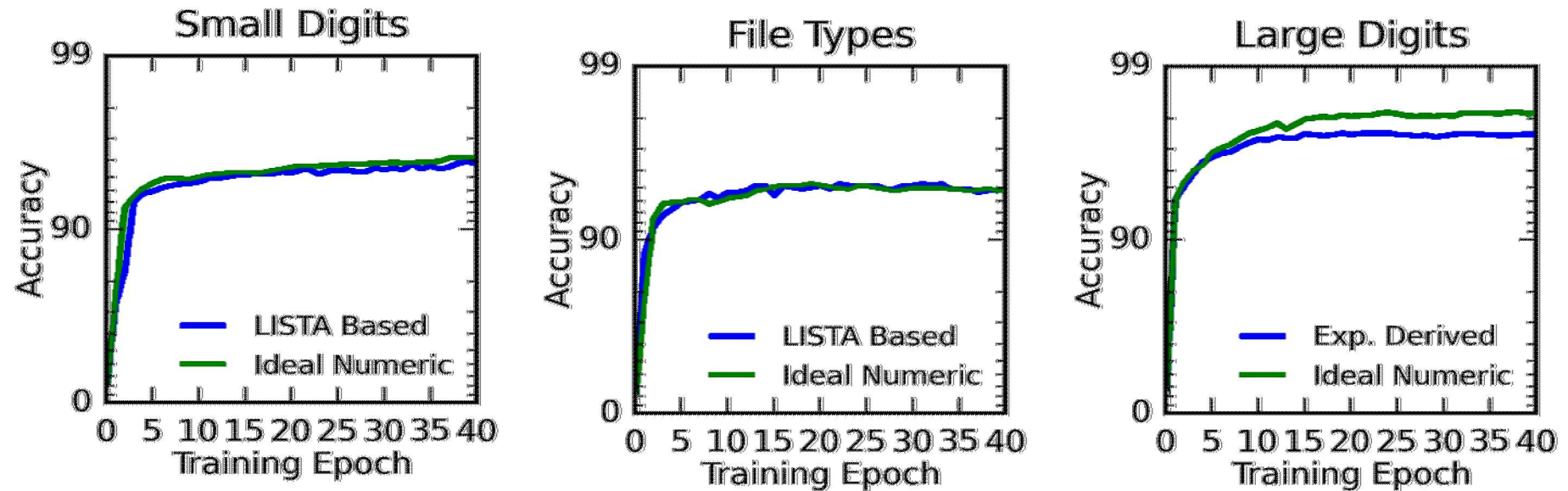


E. Fuller et al, *Adv Mater*, accepted 2017

GW Burr et al, *IEEE TED* 2015

# LISTA-device Performance for Backprop Algorithm

Increasing Network Size



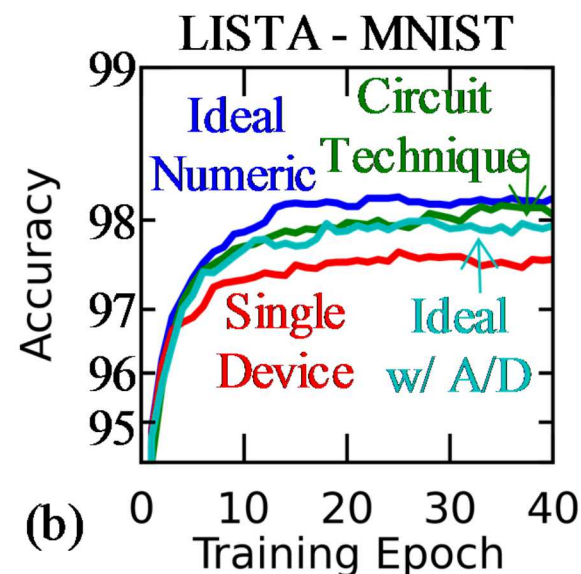
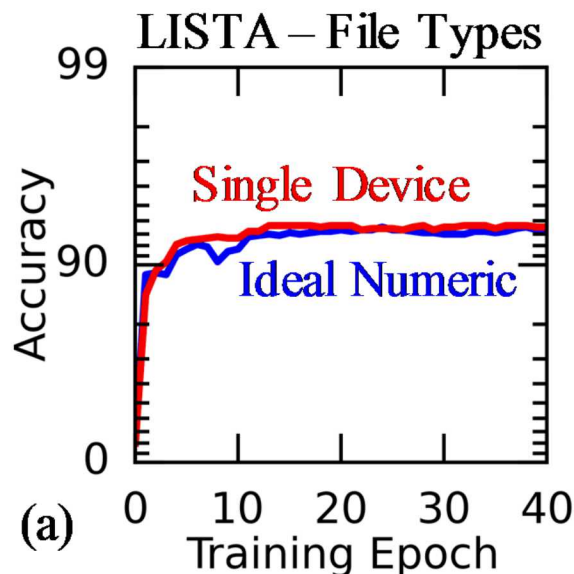
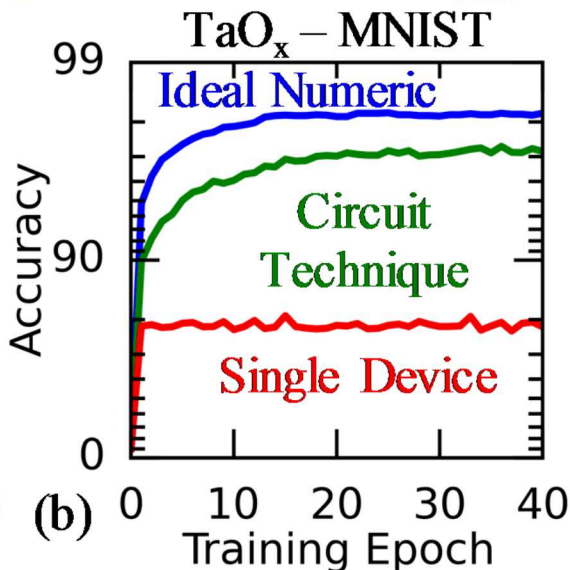
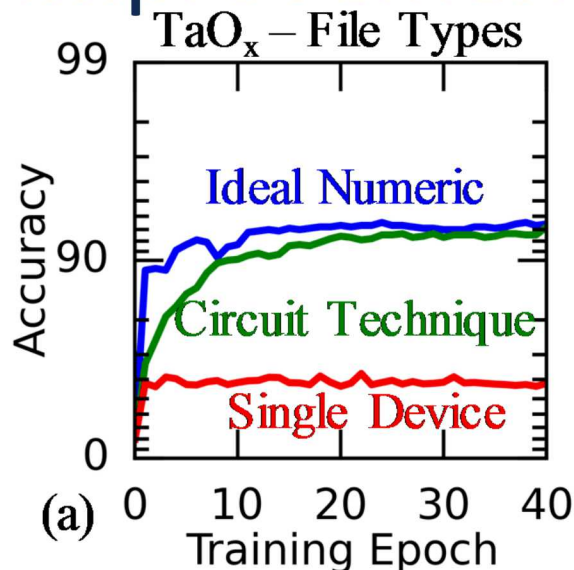
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E. Fuller et al, *Adv Mater*, accepted 2017



# Circuit-Level Improvement

- Allows much closer to ideal with high variability TaOx device
- LISTA achieves essentially perfect accuracy
- Requires tradeoff of energy/latency for accuracy – exact tradeoff depends on algorithm reqs.



Agarwal et al, submitted 2017

# Energy and Latency Comparison

Overview		Digital SRAM	Digital ReRAM	Analog ReRAM Crossbar
Equivalent Area ~450 1k× 1k matrices		400 mm <sup>2</sup>	32 mm <sup>2</sup>	11 mm <sup>2</sup> [64nm pitch]
Total Time <i>[per cycle]</i>		~ 100μ s	~ 60μ s	~ 5μ s
Total Energy <i>[per cycle]</i>		~ 1000 nJ	~ 700 nJ	~ 15 nJ
Matrix Storage Area		95%	50%	17%
Periphery Area		5%	50%	100% (crossbar is above periphery)
Matrices per 400 mm <sup>2</sup> Chip		~450	~5,500	~15,000
The above figures do not include a SIMD engine or on-chip routing fabric, and are based on a 14nm FinFET process.				

# Energy Analysis

Per-Component Breakdown		Digital SRAM	Digital ReRAM	Analog ReRAM Crossbar
Matrix Storage 1024× 1024 Digital: 8 bits/value Analog: 1 cell/value [Values are per-array]	Area	800,000 μm <sup>2</sup>	35,000μ m <sup>2</sup>	10,000μ m <sup>2</sup>
	Read	30 nJ / 15μ s	15 nJ / 4μ s	~ 3 nJ / ~ 1.5μ s
	Read Transpose	300 nJ / 65 μs	15 nJ / 4μ s	~ 3 nJ / ~ 1.5μ s
	Write	30 nJ / 15μ s	50 nJ / 45 μs	~ 3 nJ / ~ 1.5μ s
Multiply Accumulators [256 in parallel]	Area	19,000μ m <sup>2</sup>		Performed by crossbar
	Run [1M ops]	200 nJ / 4μ s		
Output LUT [8 bit→ 16 bit]	Area	1,400μ m <sup>2</sup>		Uses Digital Methods
	Read [1K values]	1 nJ / 1μ s		
Input/Output Buffers [8 bits]	Area	13,000μ m <sup>2</sup>		
	Per Run	~ 0.1 nJ		
128 Entry 1024x8 Vector Cache (8 matrices per cache) [Values are per vector]	Area	90,000μ m <sup>2</sup>	4,000μ m <sup>2</sup>	
	Read	~ 0.1 nJ / ~ 0.2μ s	~ 1 nJ / ~ 4 ns	
	Write	~ 0.1 nJ / ~ 0.2μ s	~ 1 nJ / ~ 50 ns	
Digital ReRAM based on output from X. Dong, et. al., <i>NVSim: A Circuit-Level Performance, Energy, and Area Model for Emerging Nonvolatile Memory</i> , in IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, vol. 31, no. 7, pp. 994-1007, July 2012.				

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- **ReRAM-Based Accelerator Model**
- **Conclusion**



# Conclusion

- Dennard (constant power density) scaling has ceased and Moore's law is slowing
- As this slows, a new direction will be needed to achieve the continue the exponential improvements in performance/watt (aka energy efficiency)
- New paradigms like neuromorphic computing will be required for sub-fJ computing
- We now require a device through system design mentality
  - Motivation behind CrossSim
- Oxide-based resistive memory offers intriguing device options for both eras
- Novel lithiated device LISTA and circuit techniques offer significant potential in the development of a low energy neural accelerator

# Thank you!



# Acknowledgements

- This work is funded by Sandia's Laboratory Directed Research and Development as part of the Hardware Acceleration of Adaptive Neural Algorithms Grand Challenge Project
- Many shared ideas among collaborators:
  - DOE BIS: John Shalf, Ramamoorthy Ramesh, Patrick Nealeau
  - Dave Mountain, Mark McLean, US Government
  - Stan Williams, John Paul Strachan, HPL
  - Jianhua Yang, U Mass
  - Hugh Barnaby, Mike Kozicki, Sheming Yu, ASU
  - Sayeef Salahuddin, UC Berkeley
  - Engin Ipek, U Rochester
  - Tarek Taha, U Dayton
  - Paul Franzon, NC State University
  - Dhireesha Kudithipudi, RIT
  - Alberto Saleo, Stanford
  - Dozens of others...
- **We are especially interested in collaborations on cross-sim!**

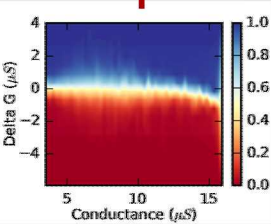
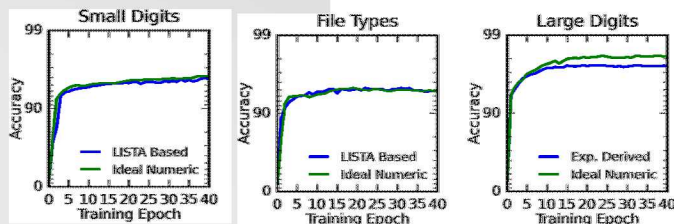
# Backup Slides



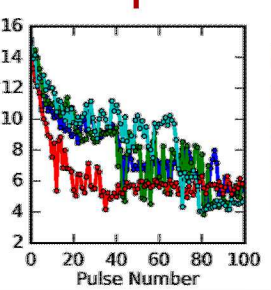
# Energy Analysis

Analog Breakdown Values are per indicated operation	Area	Energy	Latency
Array [1024× 1024]	4,300μ m <sup>2</sup>	~ 0.2 nJ read ~ <b>2 nJ</b> write	~ 1 ns (propagation)
Temporal Drivers [1024 rows]	460μ m <sup>2</sup>	~ 2 pJ read ~ 0.3 nJ write	<b>1 ns</b> × 2 <sup>bits</sup>
Voltage Drivers [1024 cols; 16 voltages]	5,000μ m <sup>2</sup>	~ 2 pJ read ~ 0.3 nJ write	≤ 1 ns
Integrators/ADCs (reads only)	3,000μ m <sup>2</sup>	~ <b>2 nJ</b>	<b>1 ns</b> × 2 <sup>bits</sup>

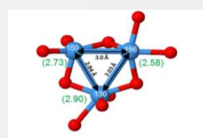
# Multiscale CoDesign Model: Neuromorphic Crossbar Accelerator



**Sandia Cross-Sim:**  
Translates device measurements and crossbar circuits to algorithm-level performance



**Memristor  
Fabrication and  
measurements  
in MESAFab**



**DFT of model of oxide  
physics, bands**

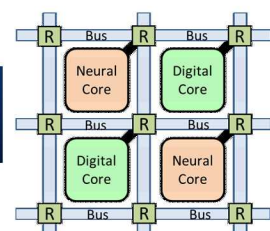
**Target Algorithms**

- Deep Learning
- Sparse Coding
- Liquid State Machines

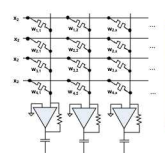
**Algorithms**



**Architecture**



**Modified McPAT/CACTI:**  
Model performance and energy requirements

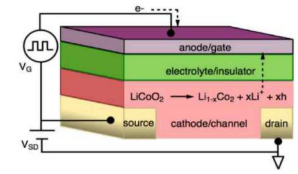


**Circuits**

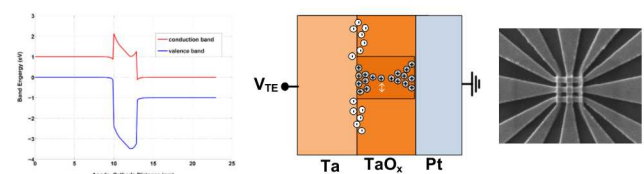


**Sandia's Xyce Circuit Sim:** Simulate crossbar circuits based on our devices

**Devices**

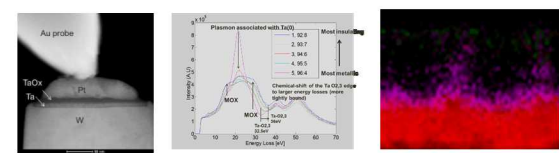


**Drift-diffusion model of ReRAM band diagram & transport (REOS, Charon)**



**Materials**

**In situ TEM of filament switching:** Use DFT model to interpret EELS signature



# Beyond Moore Co-design Framework

10,000x improvement: 20 fJ per instruction equivalent

Modeling

Experimental

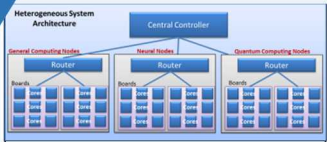
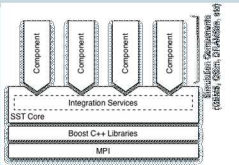
## Algorithms and Software Environments

- Application Performance Modeling



## Computer System Architecture Modeling

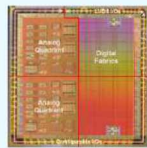
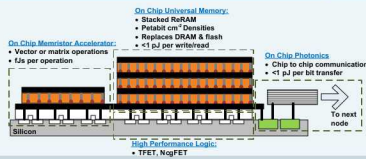
- Next generation of Structural Simulation Toolkit
- Heterogeneous systems HPC models



Algorithms & SW Environments

## Microarchitecture Models

- McPAT, CACTI, NVSIM, gem5



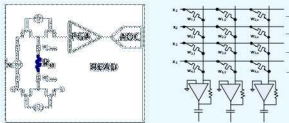
## Component Fabrication

- Processors, ASICs
- Photonics
- Memory

Hardware & Circuit Architectures

## Circuit/IP Block Design and Modeling

- SPICE/Xyce model



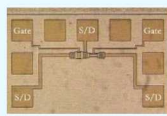
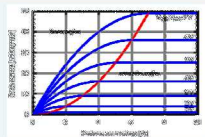
## Test Circuit Fab and Measurement

- Subcircuit measurement

Comm., Memory & Computation Devices

## Compact Device Models

- Single device electrical models
- Variability and corner models

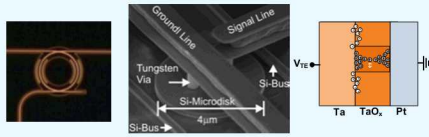


## Device Measurements

- Single device electrical behavior
- Parametric variability

## Device Physics Modeling

- Device physics modeling (TCAD)
- Electron transport, ion transport
- Magnetic properties

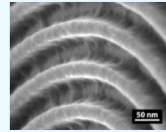
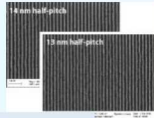
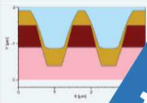


## Device Structure Integration and Demonstration

- Novel device structure demonstration

## Process Module Modeling

- Diffusion, etch, implant simulation
- EUV and novel lithography models

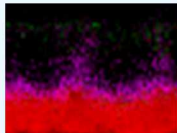
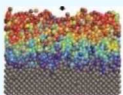


## Process Module Demonstrations

- EUV and novel lithography
- Diffusion, etch, implant simulation

## Atomistic and Ab-Initio Modeling

- DFT – VASP, Socorro
- MD – LAMMPS



## Fundamental Materials Science

- Understanding Properties/Defects via Electron, Photon, & Scanning Probes
- Novel Materials Synthesis

Materials

Example activities within a MSCD framework

Materials

Devices

Architectures

Algorithms



### Integrated Storage Class Memory

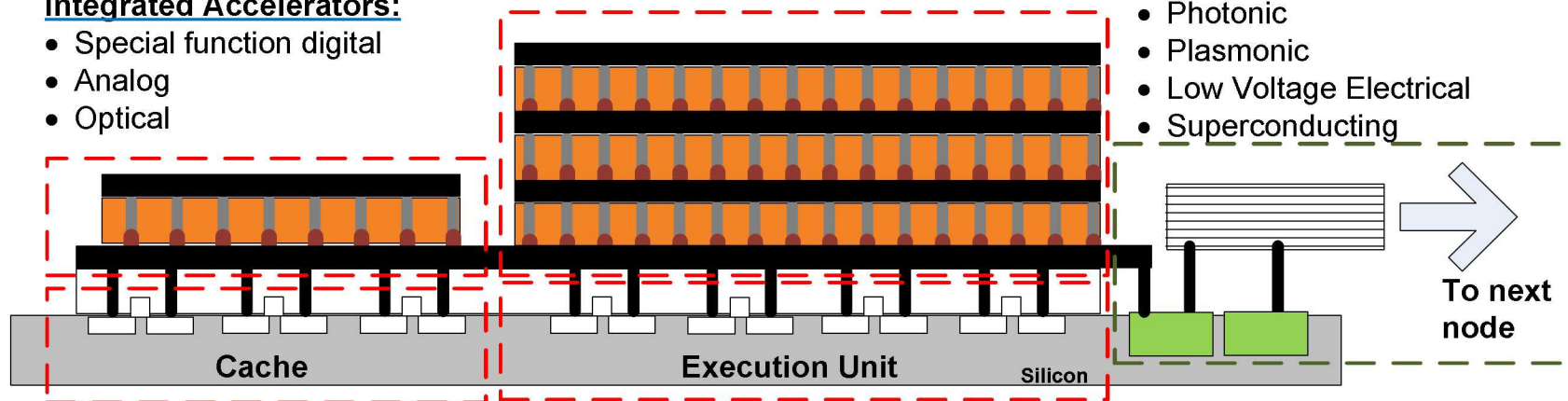
- ReRAM
- STT Magnetic RAM
- CBRAM
- Ferroelectric RAM

### Integrated Accelerators:

- Special function digital
- Analog
- Optical

### Integrated Communication Devices

- Photonic
- Plasmonic
- Low Voltage Electrical
- Superconducting



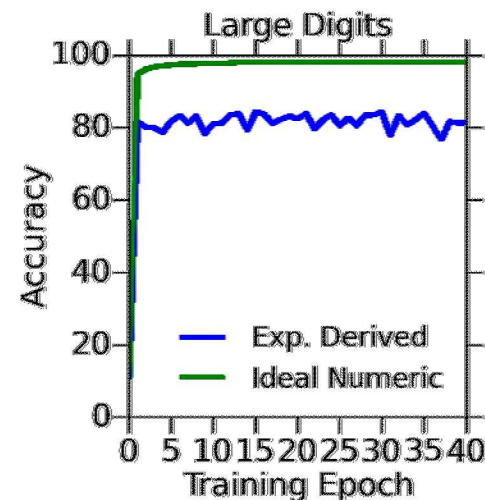
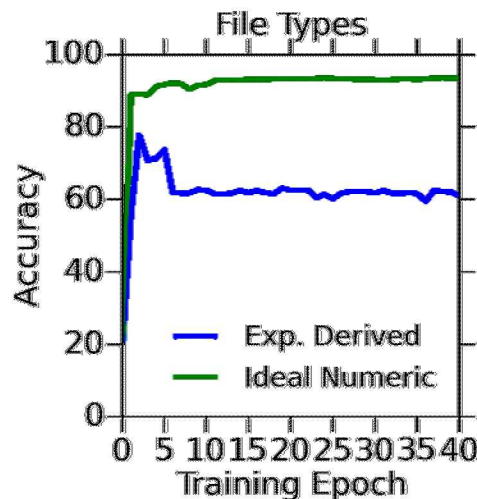
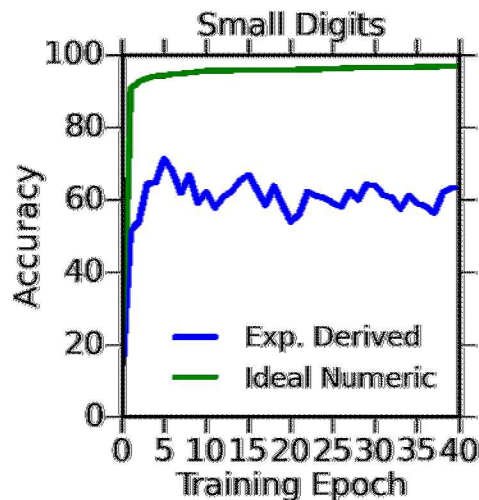
### Low voltage high performance logic:

- Tunnel-FET
- Negative Cg FET
- Single Electron Transistor



# TaOx ReRAM in Backprop Training (10ns)

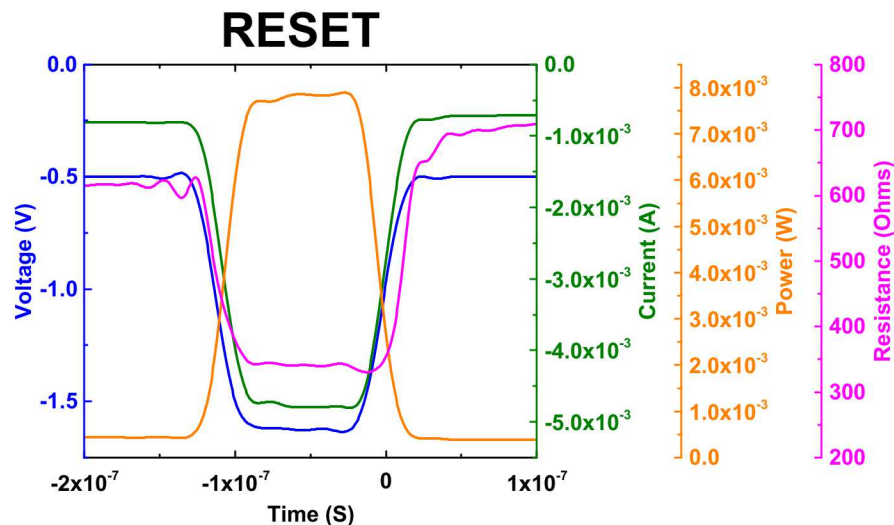
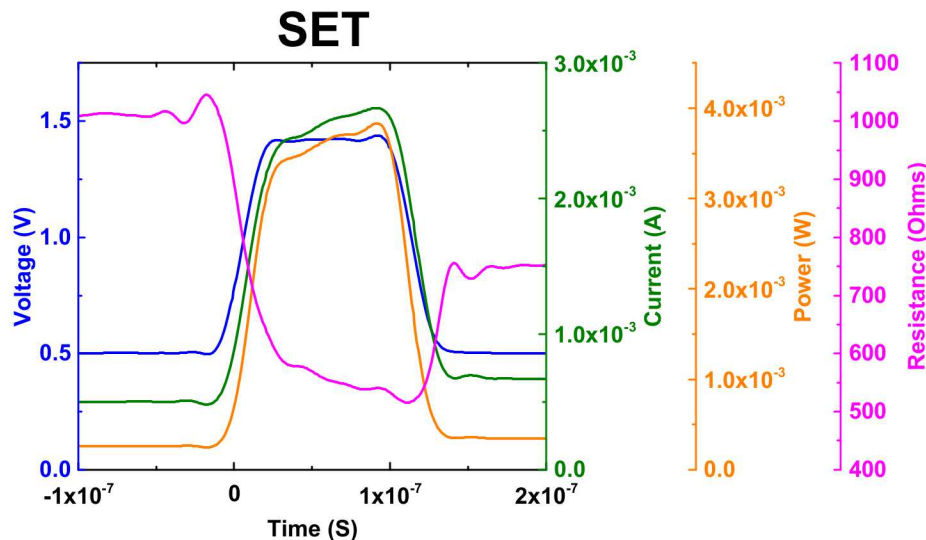
Increasing Network Size



Data set	# Training Examples	# Test Examples	Network Size
UCI Small Digits[1]	3,823	1,797	64×36×10
File Types[2]	4,501	900	256×512×9
MNIST Large Digits[3]	60,000	10,000	784×300×10

**How can training accuracy be improved?**

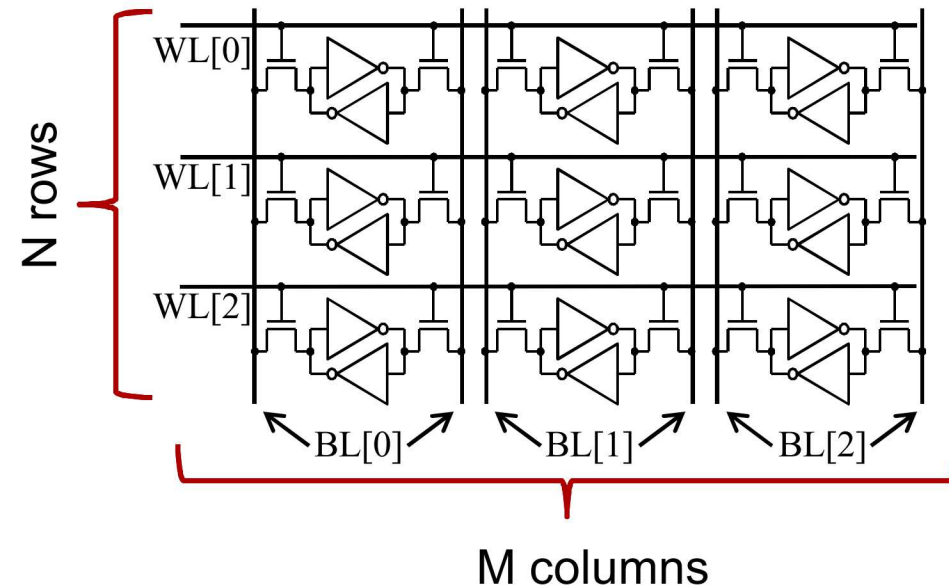
# Switching Power & Energy Measurement Sandia National Laboratories



- Energy determination requires fast pulsed measurements:
- Can measure resistance change during pulsed switching with pulsewidths > 100 ns and edgetimes > 10 ns
- $E = \int_0^t P(t)$ 
  - $\approx 800$  pJ (RESET)
  - $\approx 400$  pJ (SET)
- Wasted power/energy past first  $\sim 1$  ns of pulse
- Lower energy with high resistance devices, sub-ns pulse
  - > 1pJ demonstrated @ <1ns in similar TaOx device (by HP)

# Theoretical Efficiency Analysis

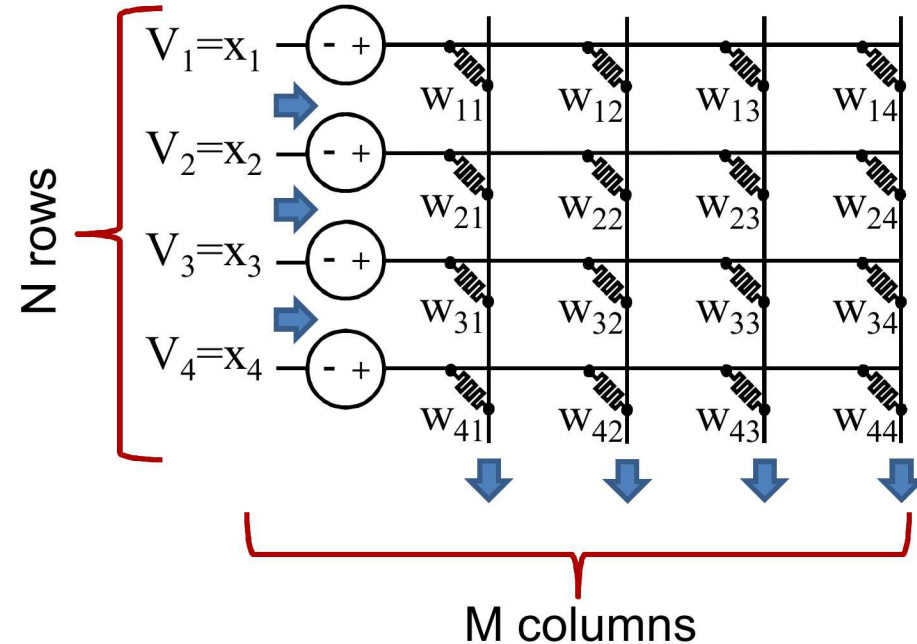
## SRAM crossbar:



SRAMs must be read one row at a time  
 → charges M columns;  
 $E = N \text{ Rows} \times O(N) \text{ wire length} \times M \text{ Columns}$   
 $\sim O(N^2 \times M)$

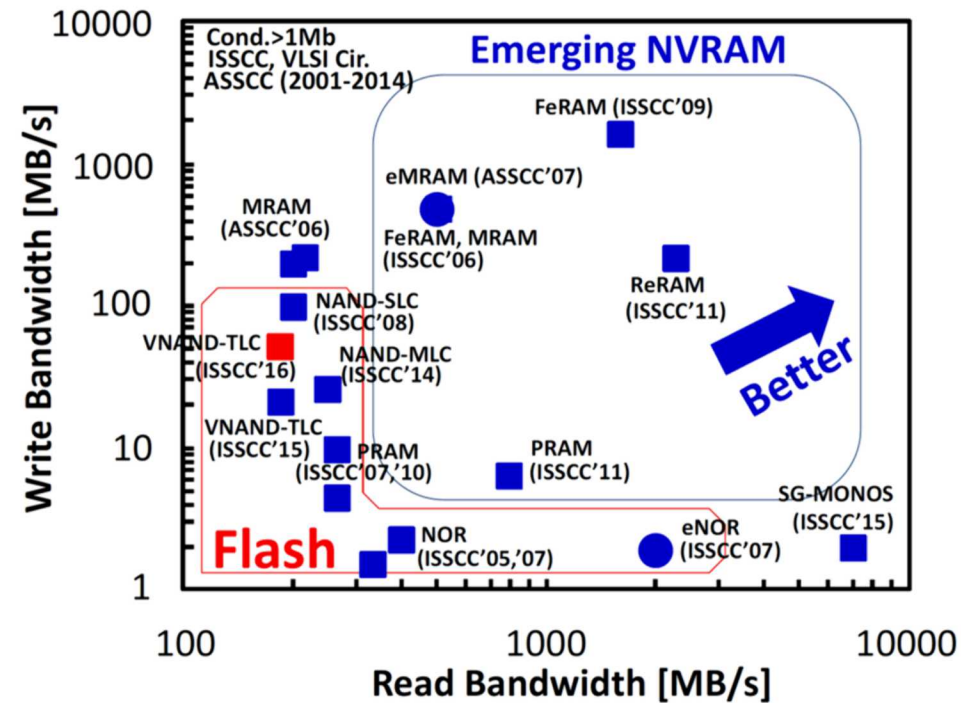
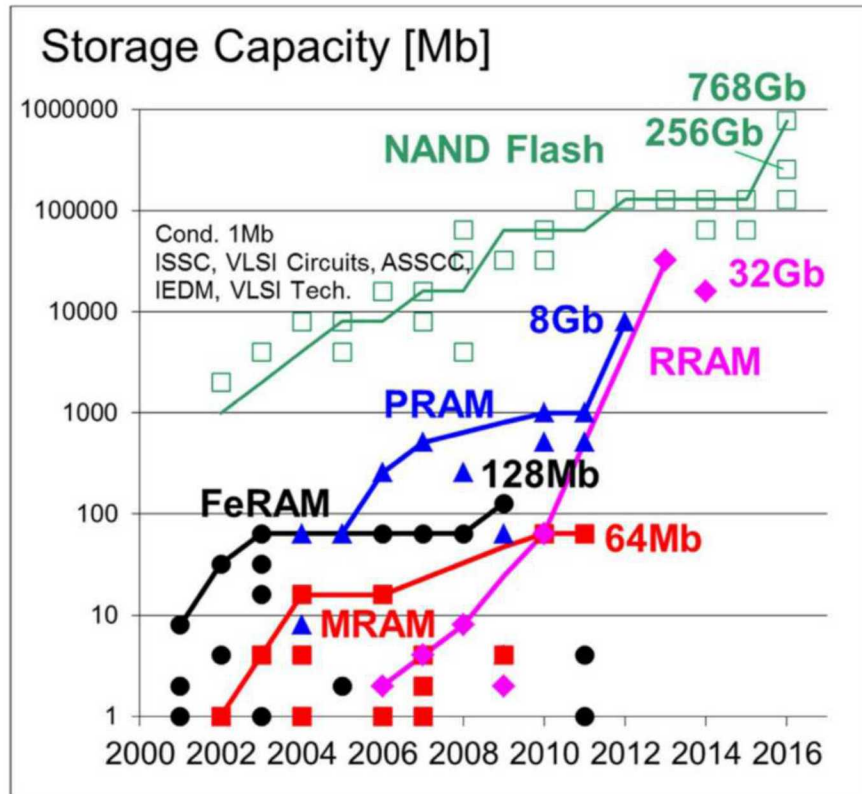
**Implication: Crossbar is  $O(N)$  better than SRAM in energy consumption for vector-matrix multiply computations**

## ReRAM crossbar:



Energy to charge the crossbar is  $CV^2$ ;  
 $E \propto C \propto \text{number of RRAMs} \propto N \times M$   
 $\sim O(N \times M)$

# Technological Considerations: Trends

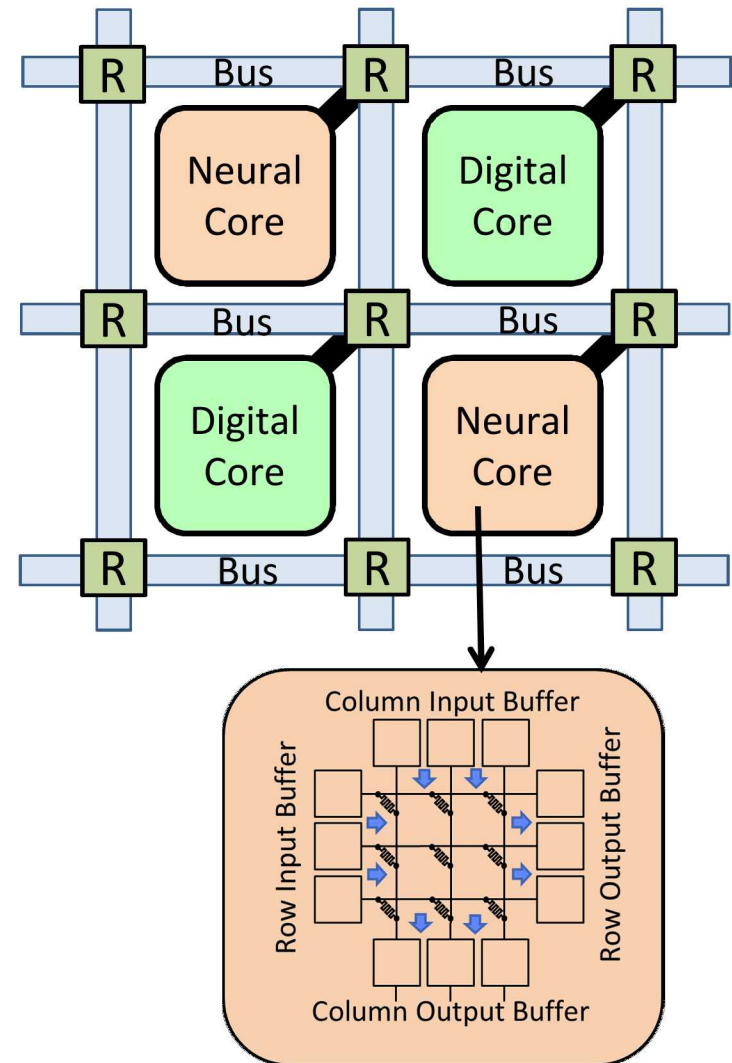


ISSCC 2016 Trends Report



# HAANA Crossbar Accelerator Design Sandia National Laboratories

- Initial work by several groups indicates order of magnitude energy efficiency gains are possible using a ReRAM accelerator
- The assumptions and outcomes of these models vary significantly
- HAANA goal: develop a Multiscale CoDesign Framework which can evaluate our neural crossbar accelerator algorithms, architectures, and devices on a “level playing field”
- Evaluate architectures and devices for **accuracy, energy, perf.**
- Once a clear energy advantage demonstrated, move forward with technology development



# How can we get to fJ computing?

Description	NPU-1	NPU-2	NPU-3	TrueNorth
System clock frequency	100kHz	1 MHz	10 MHz	1 kHz
Synapses per neuron	500	500	500	256
Average energy per device update	1 fJ	1 fJ	10 aJ	26 pJ
Energy per update op cycle (per core)	250pJ	250pJ	2.5pJ	
Operations per second (per core)	250 GOPs	250 GOPs	250 GOPs	
Single core max power	25 uW	250 uW	25 uW	
Chip Area	4 cm <sup>2</sup>	4 cm <sup>2</sup>	4 cm <sup>2</sup>	4.3 cm <sup>2</sup>
Cores per layer	800 k	800 k	800 k	4 k
Layers per chip	10	100	10	1
Neurons per chip	4 B	200 B	4 B	1 M
Chip Max Power	200 W	10 kW	200 W	70 mW
Chip Max operations per second	0.2 ExaMACS	10 ExaMACS	20 ExaMACS	28 GigaOps
Operations per second per watt	10 <sup>15</sup> MACS/W	10 <sup>15</sup> MACS/W	10 <sup>17</sup> MACS/W	4x10 <sup>11</sup> Ops/W

MACS = Multiply Accumulate per Second



# How do we get to 10 fJ per inst?

- CMOS scaling not providing significant energy efficiency gains
- Many algorithmic, architectural, and device answers:
  - Neuromorphic algorithms
  - Analog accelerators
  - mV switch (e.g. TFET, NgcFET)
  - Superconducting electronics, quantum computing...
- Which horse should we bet on??
- Well...studies for each approach “prove” each respective option to be the best path forward
- Winner not yet clear, most will require major development efforts to realize full potential (\$\$)
- Need systematic, universal method to determine best approaches for further investment...